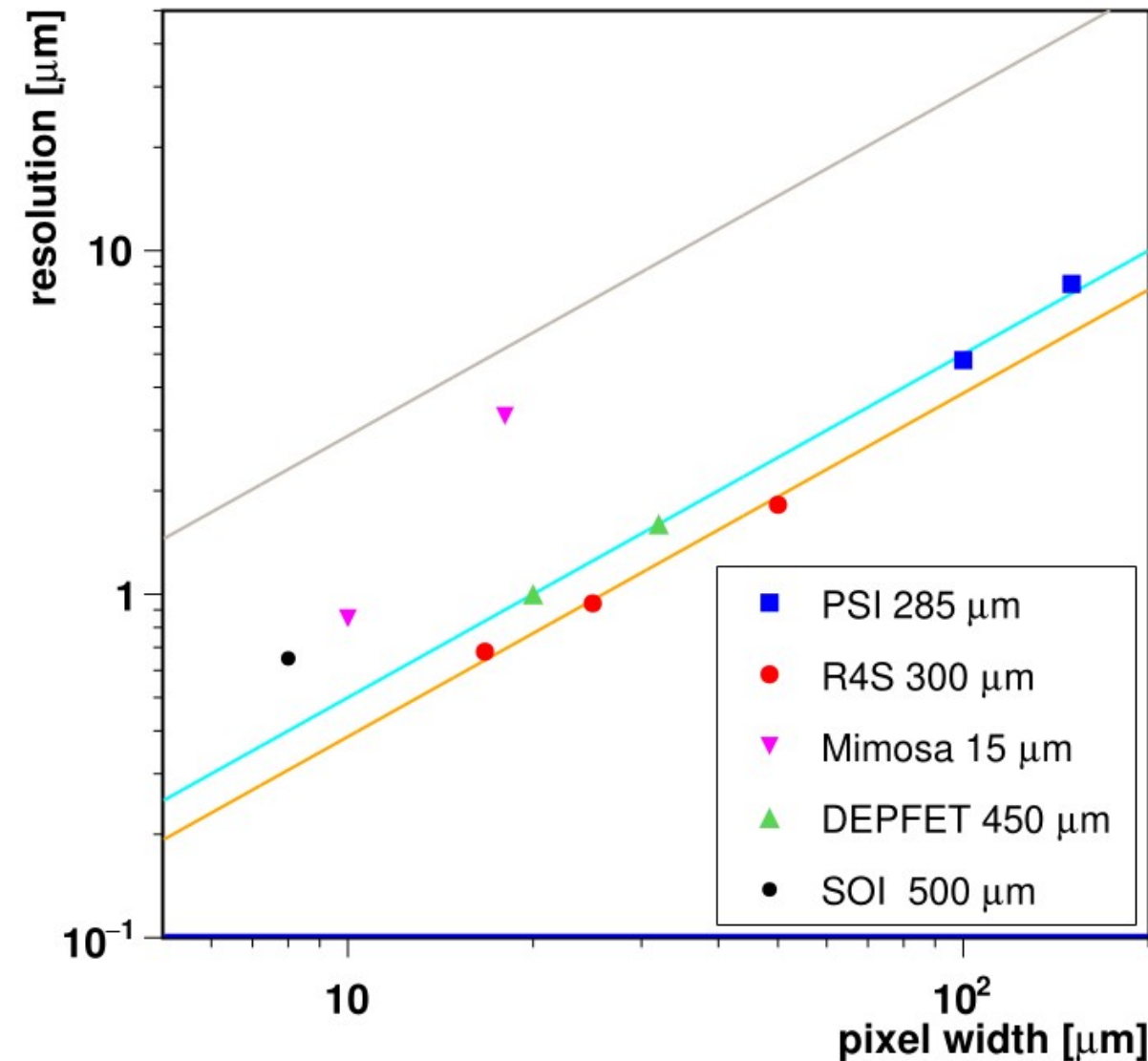


position resolution

Daniel Pitzl, DESY
DESY SiDet group, 13.1.2021



- position resolution effects
- small pixel designs
- telescope method
- three-plane method
- rotated edge-on method
- resolution summary

resolution issues

- **friends of resolution**

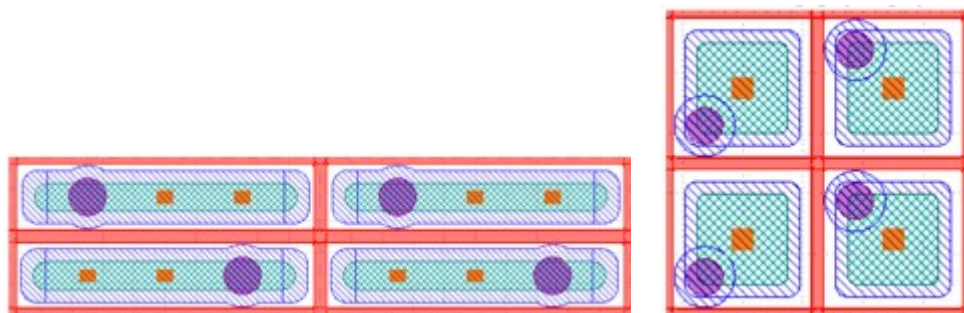
- ▶ small pixels
- ▶ optimal incidence angle
- ▶ low threshold
- ▶ thick sensors
- ▶ diffusion (vertical)
- ▶ uniform ionization
- ▶ analog readout
- ▶ 8-bit ADC or ToT
- ▶ smart clustering

- **enemies of resolution**

- ▶ large pixels
- ▶ vertical incidence
- ▶ high threshold
- ▶ thin sensors
- ▶ diffusion (inclined)
- ▶ ionization fluctuations
- ▶ binary readout
- ▶ 4-bit ADC or ToT
- ▶ cross-talk
- ▶ delta rays
- ▶ electronics noise
- ▶ radiation damage

how to measure resolution

- classical:
 - reference telescope and one device under test (DUT)
 - telescope should have better resolution than DUT
- independent:
 - multiple DUT planes
 - simple error propagation to single plane
- telescope-on-a-chip:
 - edge-on
 - need only one DUT
 - low rate (few Hz)



- 150 μm thickness (Uni HH):

- 50 $\times$ 50 and 25 $\times$ 100 μm

- 285m thickness (PSI):

- 50 $\times$ 50, 25 $\times$ 100, and
17 $\times$ 150 μm

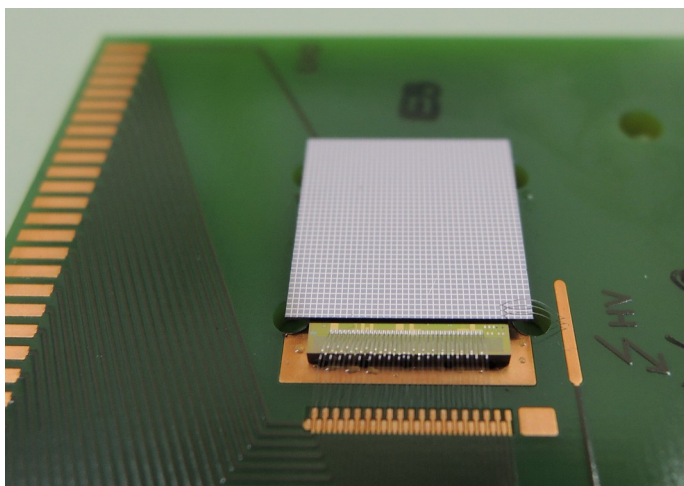
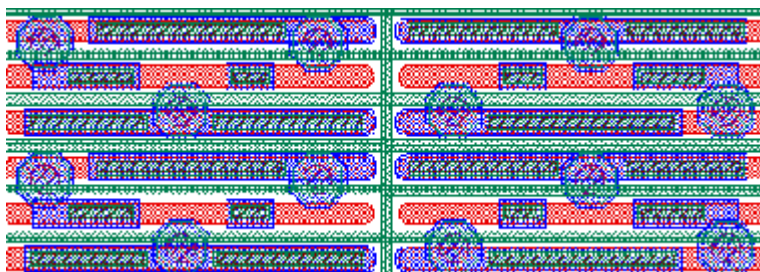
- ROC4Sens readout chip (PSI):

- 50 $\times$ 50 μm , 24'800 pixels

- flip chip bump bonding (IZM)

- analog readout, no zero suppression

- USB 2 DAQ: 180 Hz



8 $\times$ 8 mm active area



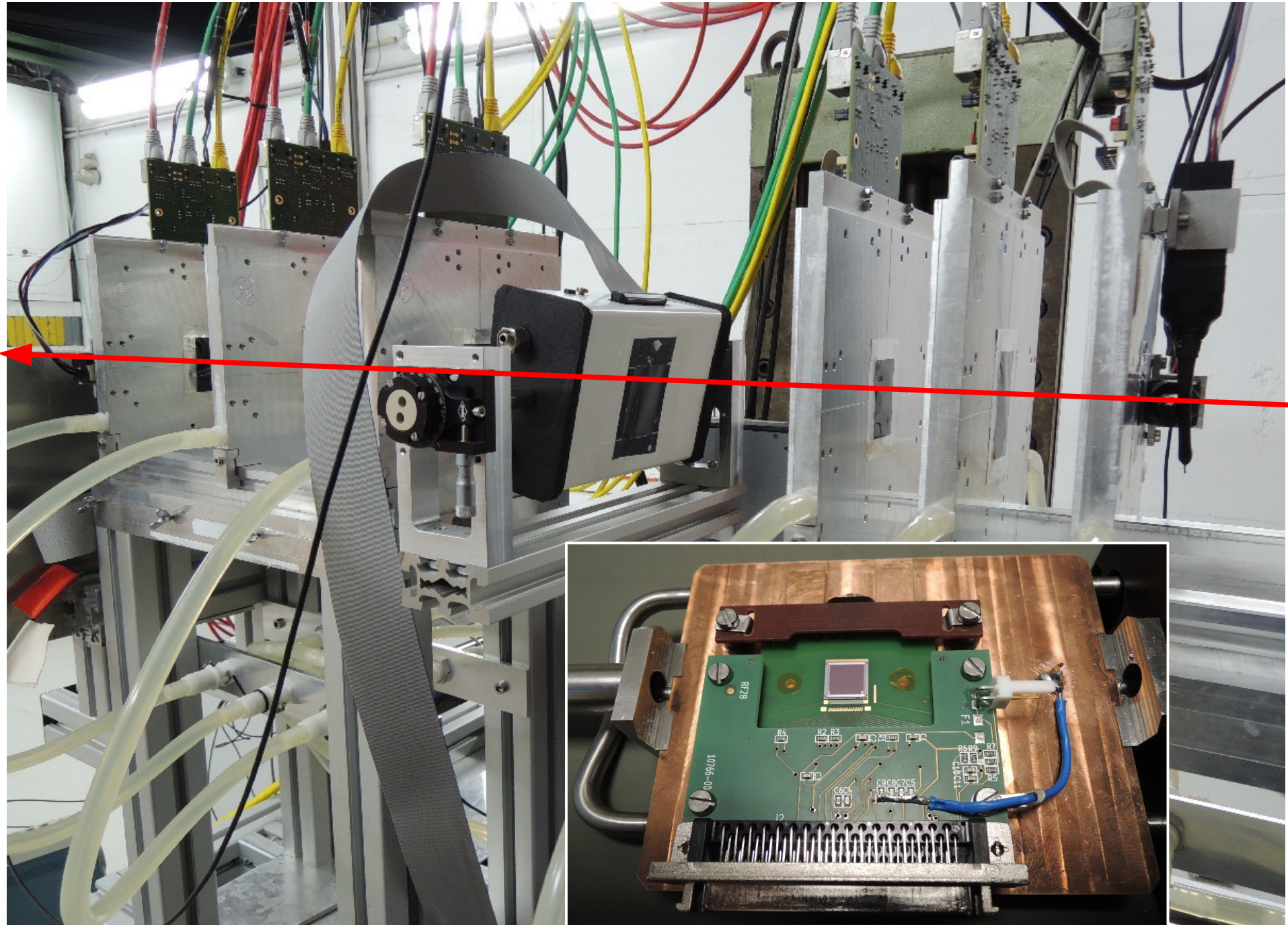
CMS Pixel test beam team



Daniel	Jörn	Erika	Irene	Finn	Faye	Caroline	Ali	Georg
Pitzl	Schwandt	Garutti	Zoi	Feindt	Bajjali	Niemeyer	Ebrahimi	Steinbrück

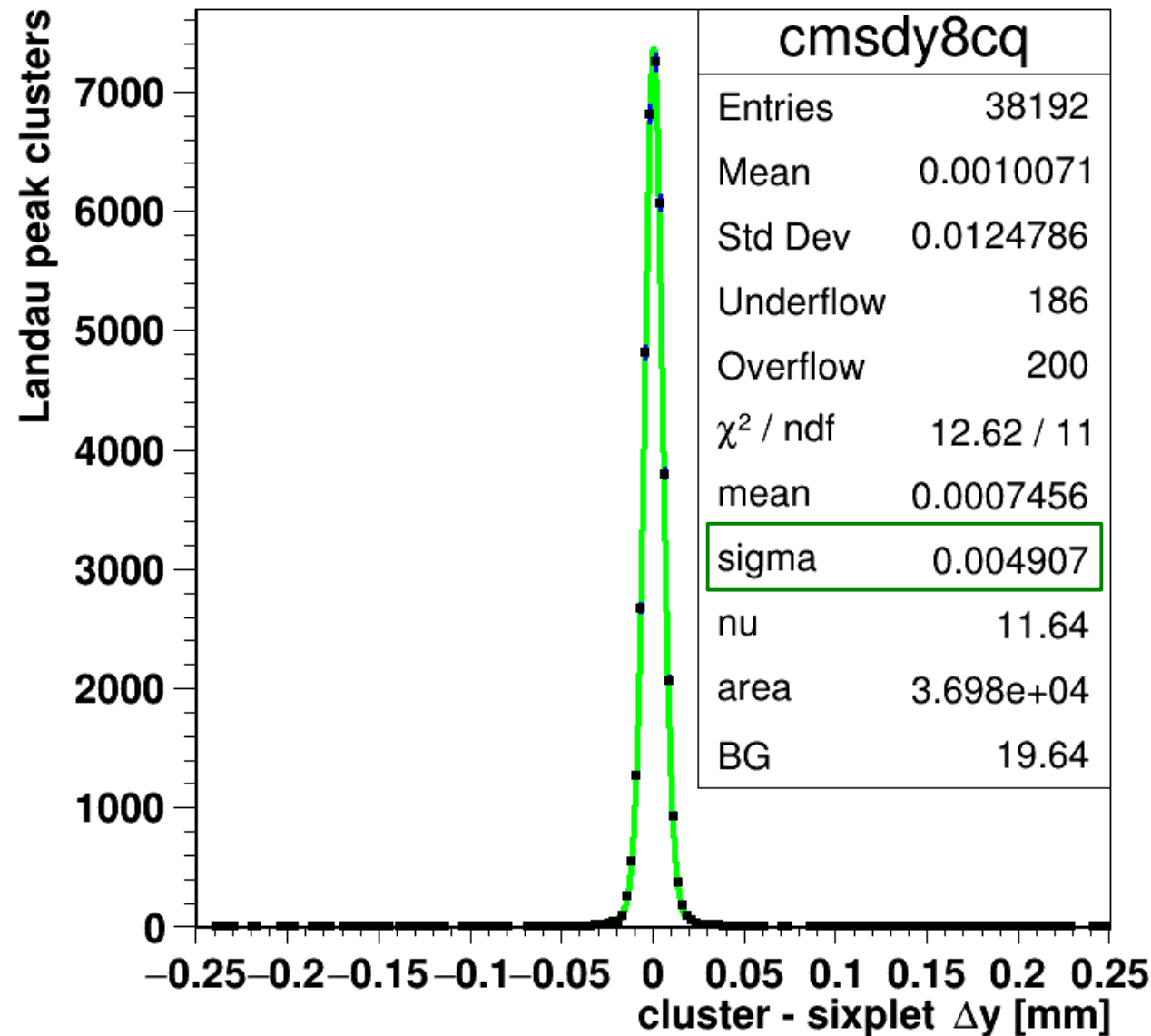
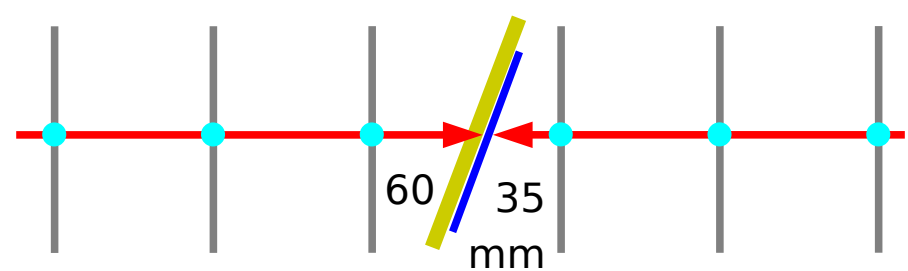
Mar 2019

DUT in the telescope



DUT-telescope residual

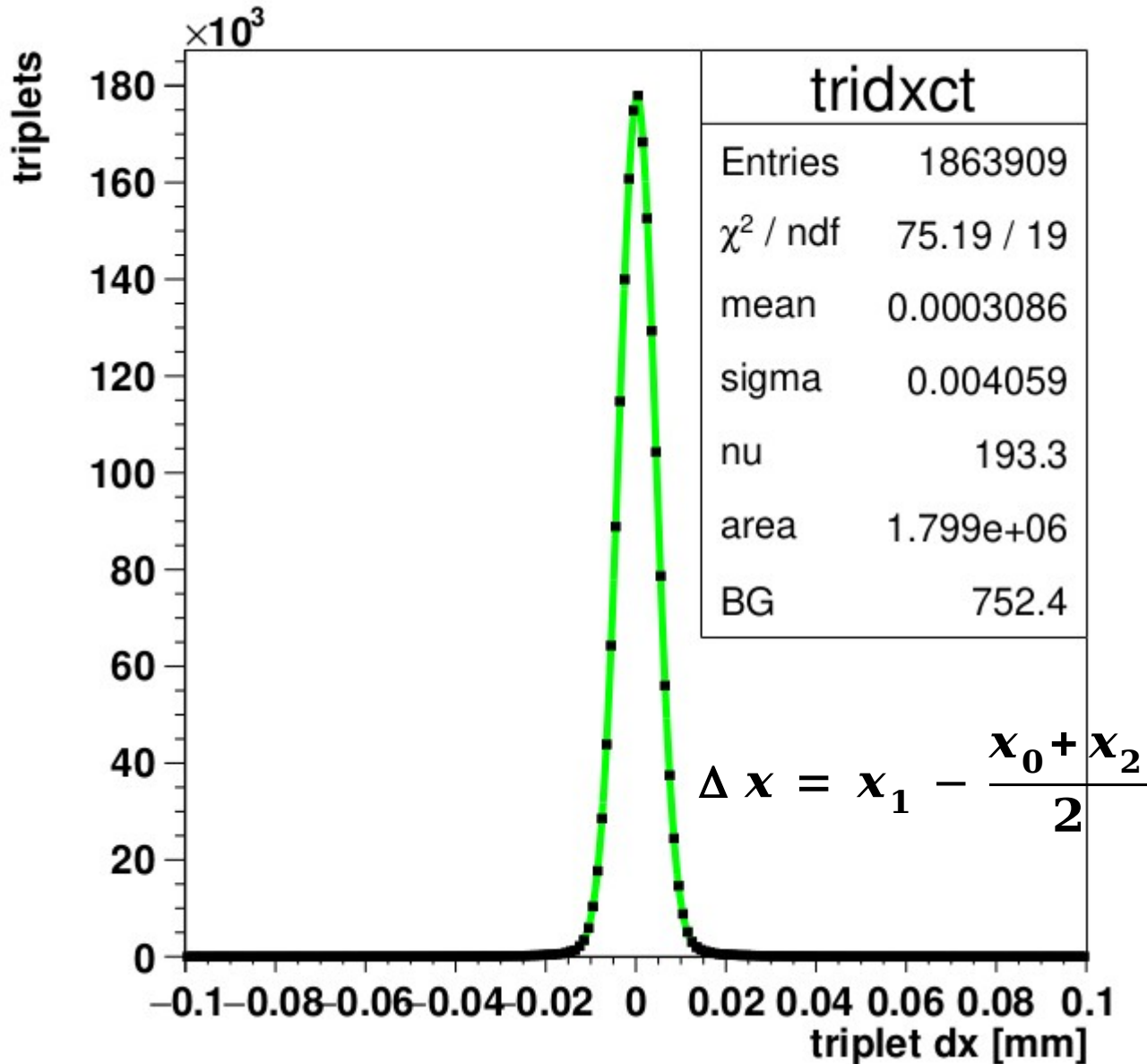
run 31166, chip 117, tilt 18°



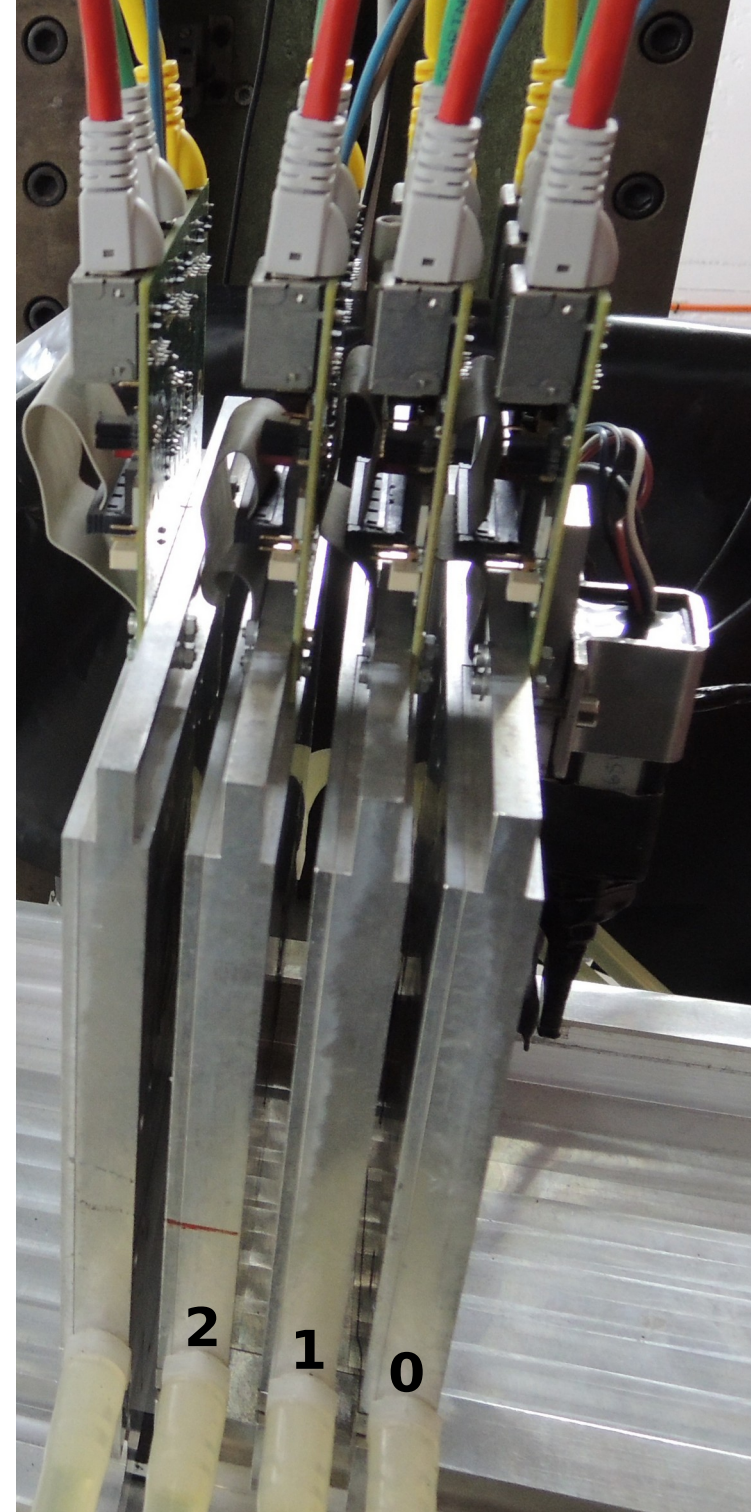
- thickness 150 μm :
 - 50×50 μm pixels
 - tilt 18°, 5.6 GeV
 - ×2 overdepletion
 - Landau peak
- residual width:
 - **4.9 μm**
- subtract track (3.4 μm):
 - **DUT 3.5 μm**

telescope resolution

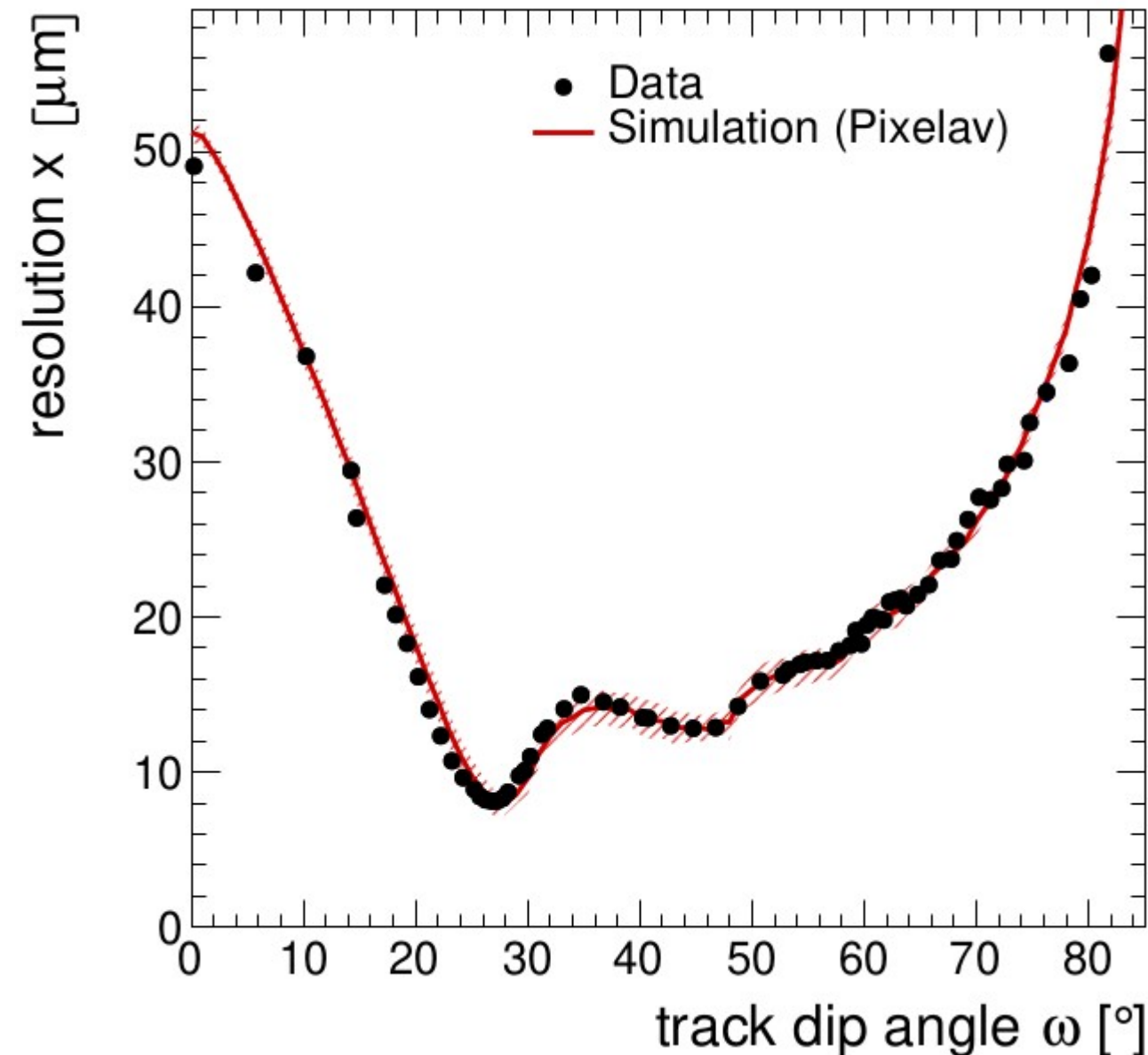
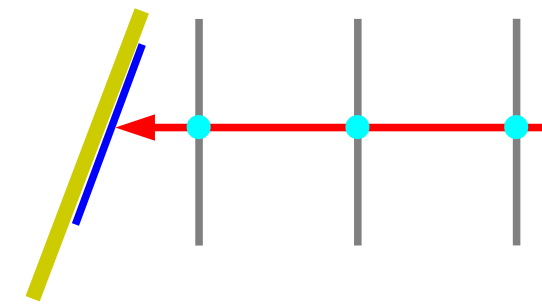
Datura, threshold 5, 5.6 GeV, 21 mm spacing



residual $4.1 \mu\text{m} \Rightarrow \text{hit } 3.3 \mu\text{m}$

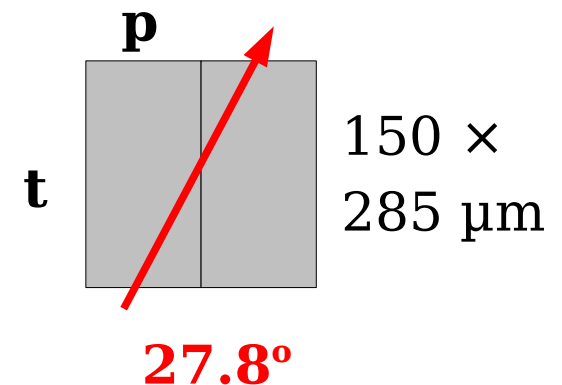


resolution vs incident angle

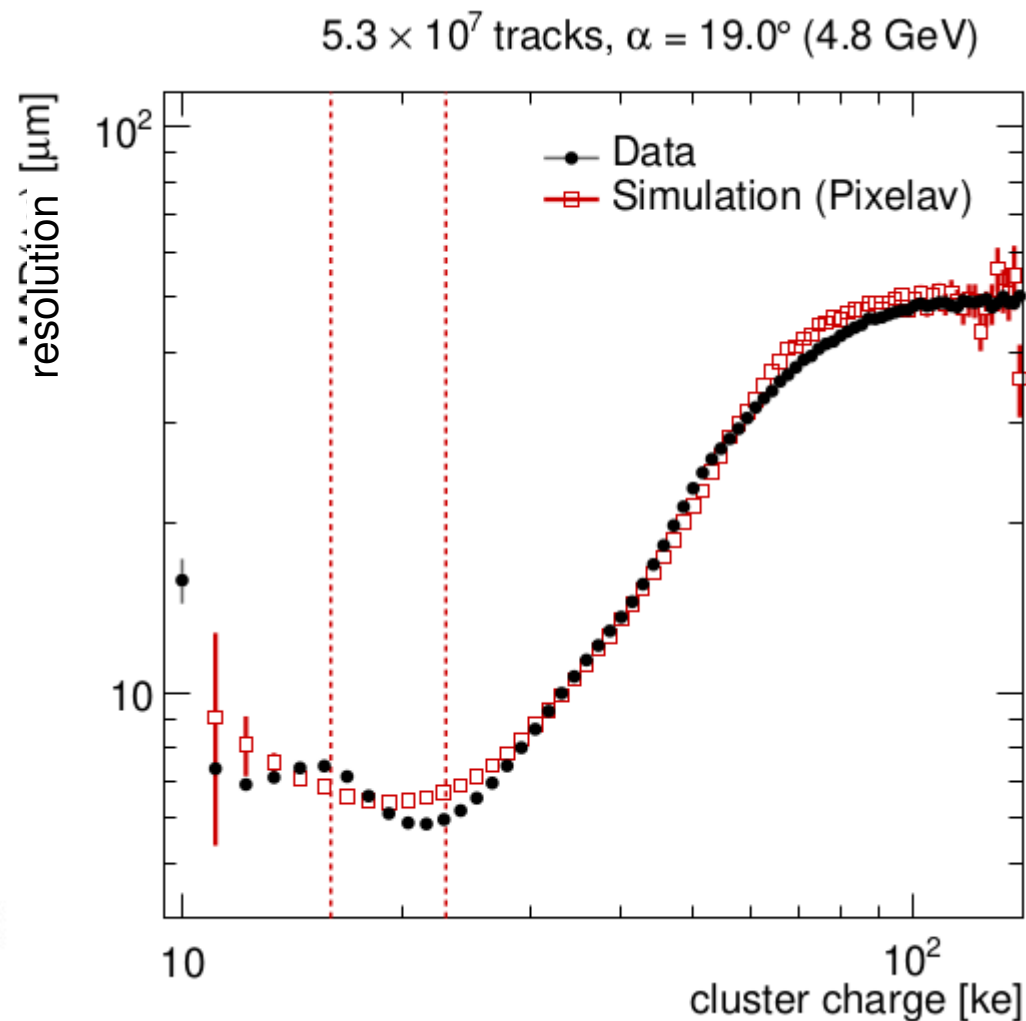
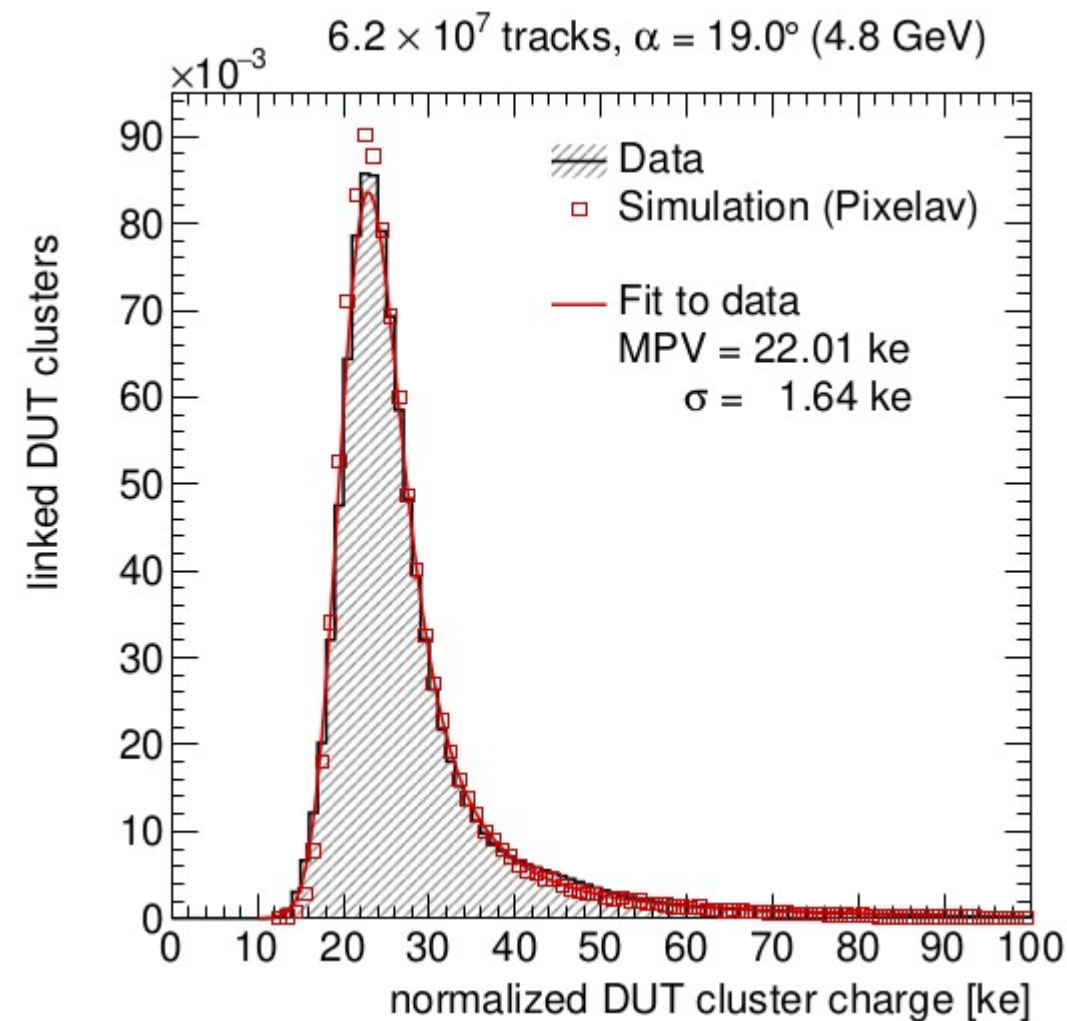


- **150 μm pixels**
 - thickness 285 μm
 - threshold 1.5 ke
- minimum:
 - **8.0 μm at 27.8°**
 - (at the Landau peak)

best dip = $\text{atan}(p/t)$

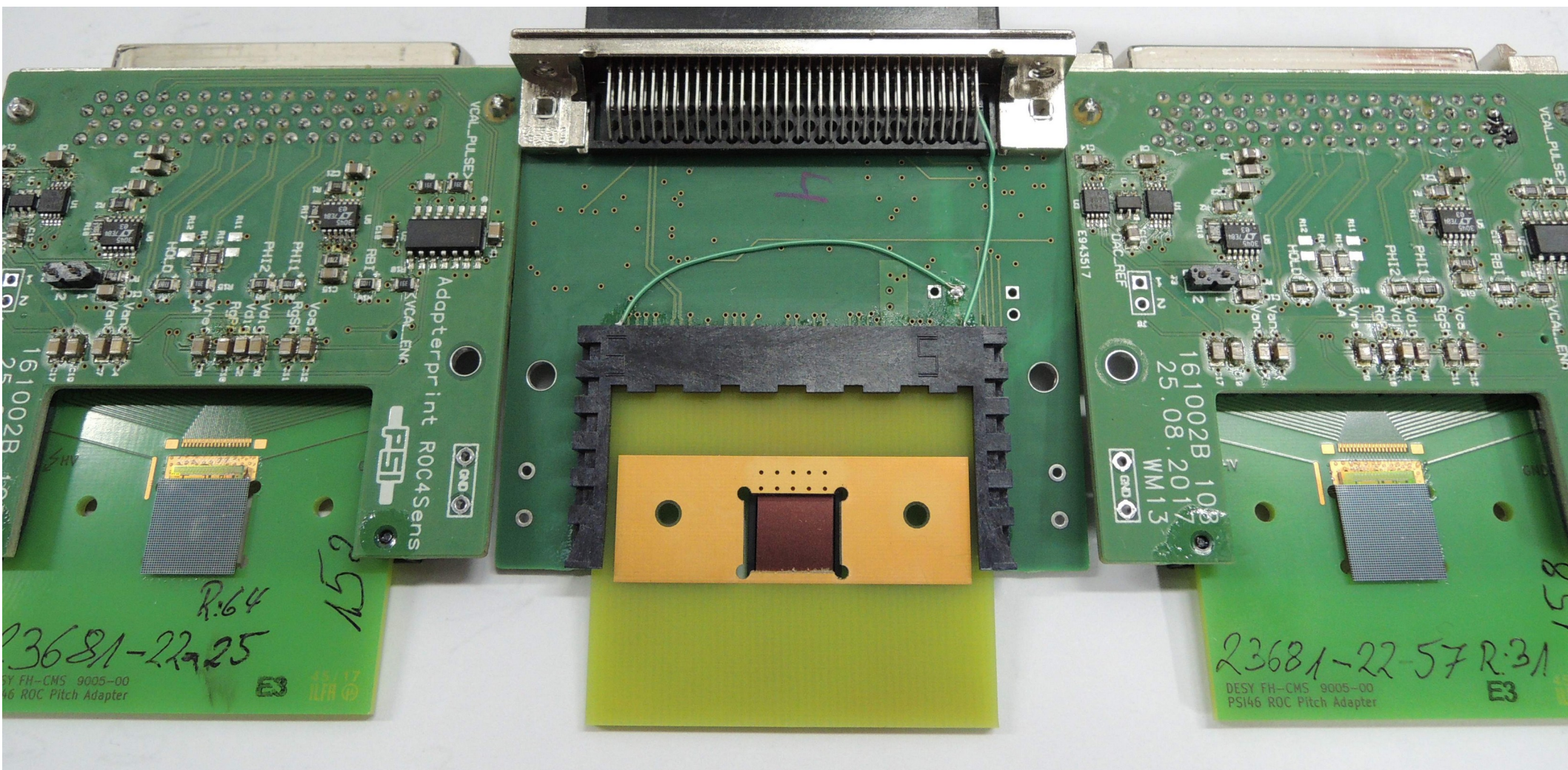


resolution vs energy loss



**delta rays in the Landau tail
spoil the resolution**

multiple DUTs

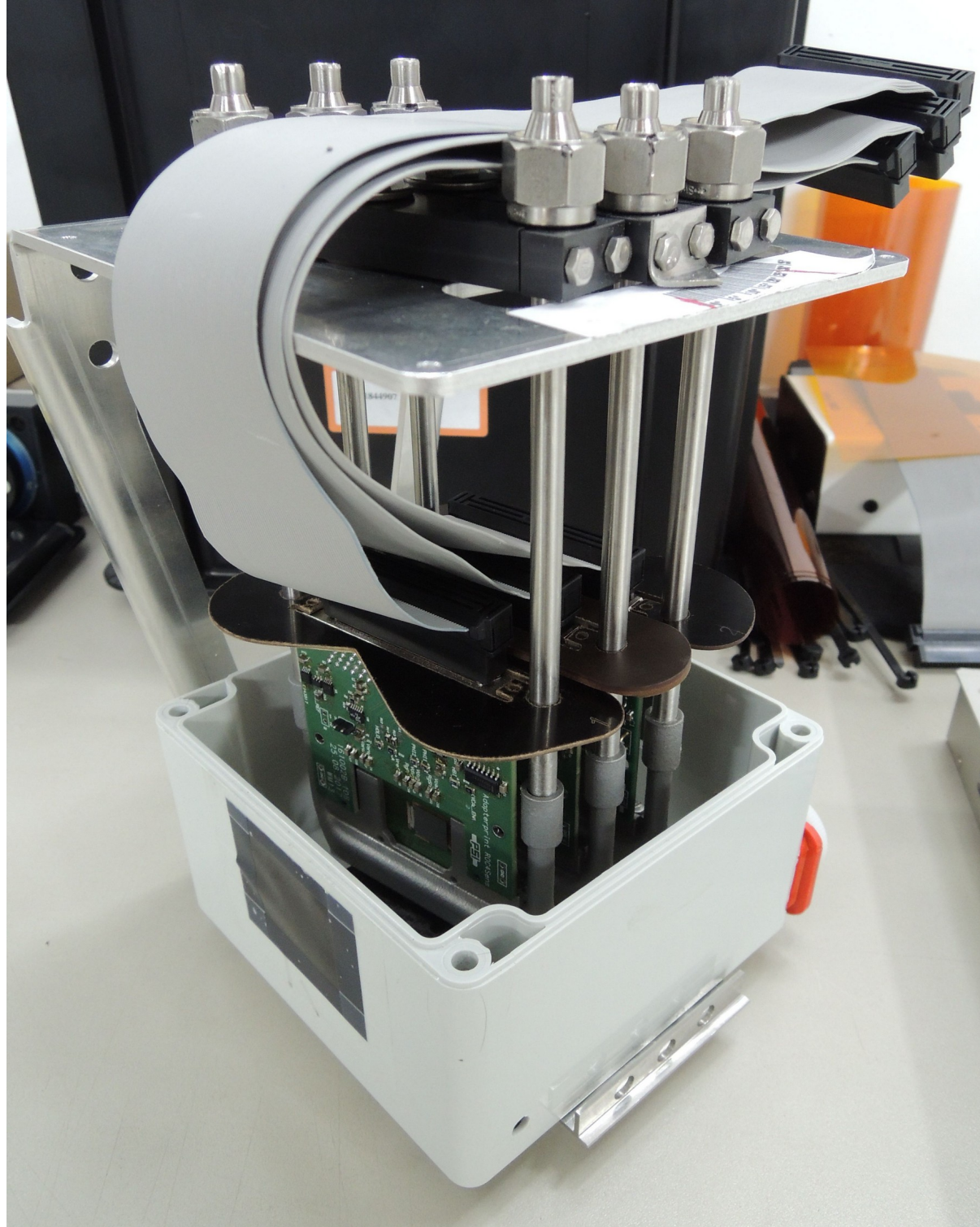


PCB with cutout: less material in the beam
 (poor cooling: not possible for irradiated samples)



Dreimaster

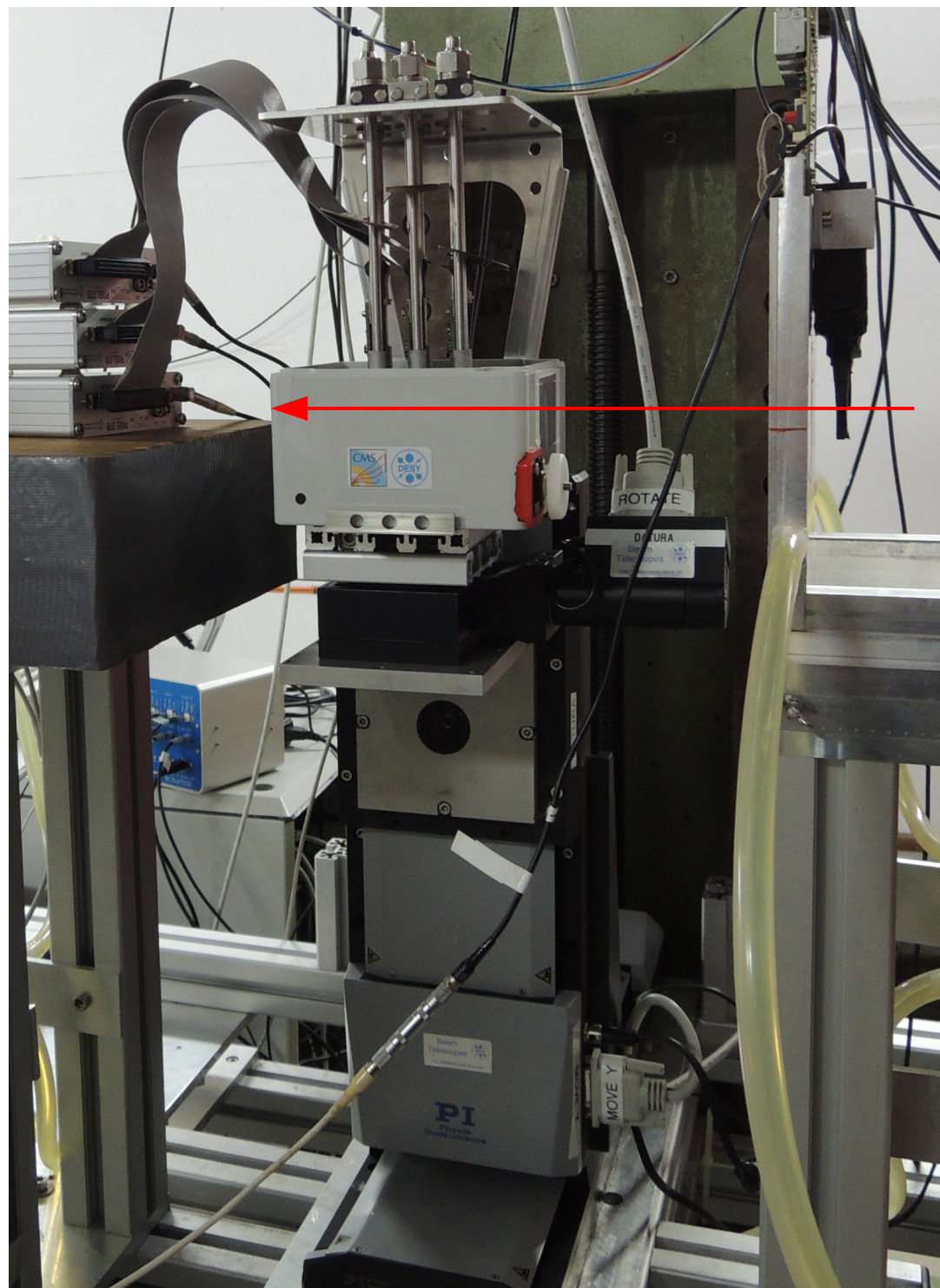
- Resolution measurement by the triplet method
- three single chip modules:
 - 20 mm spacing
 - common turn angle from 0 to 30°
 - with cooling and housing
- change of modules takes ~20 min



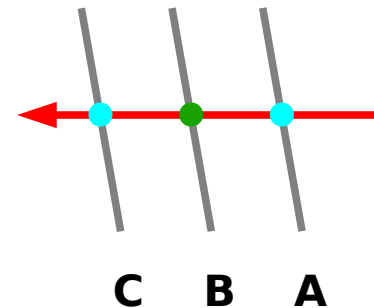


Dreimaster test beam

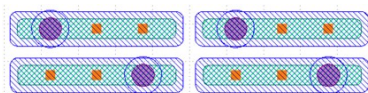
- Dreimaster mounted on PI stage:
 - x and y movement
 - θ rotation
- (telescope not used)
 - trigger scintillator



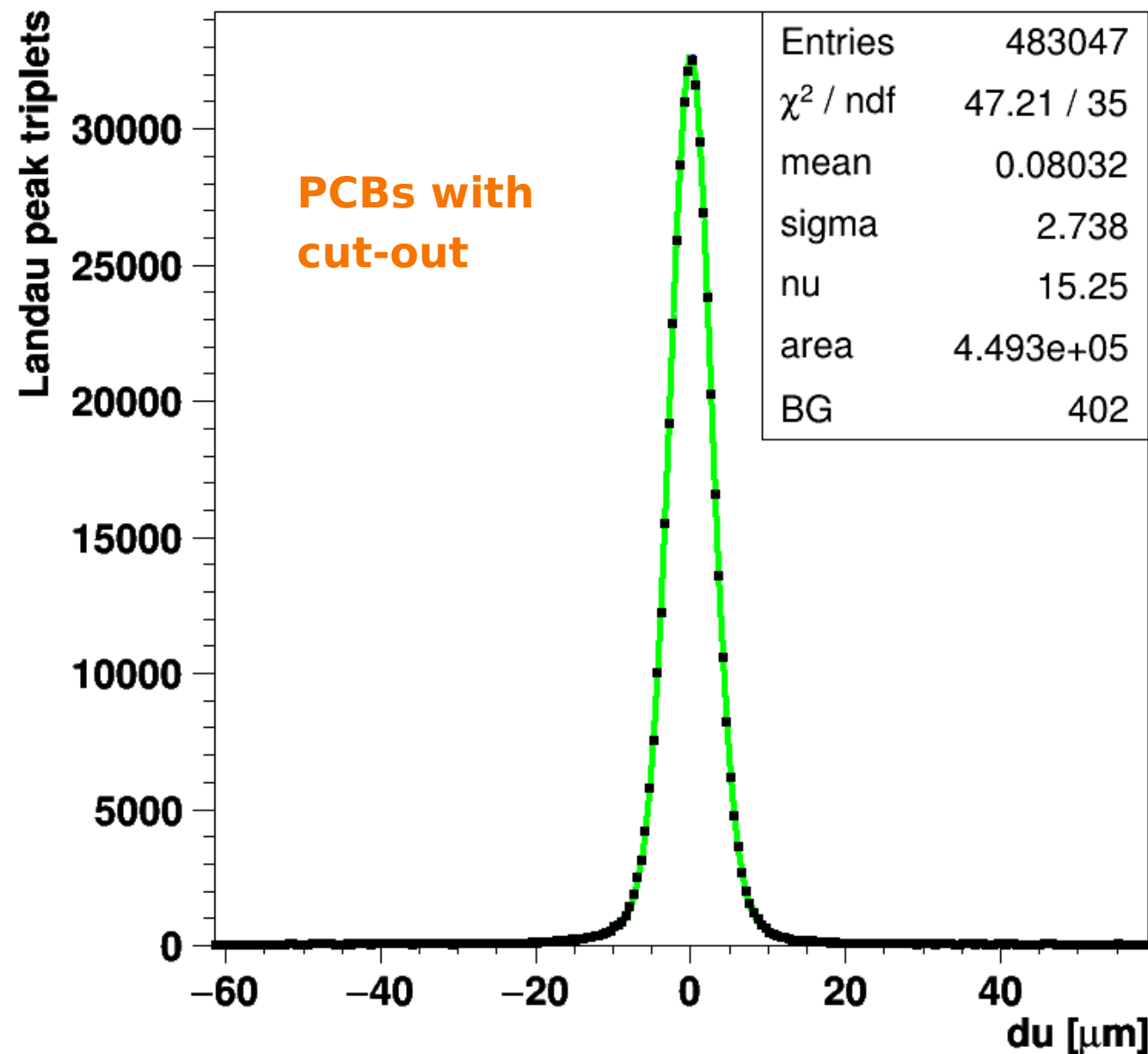
Dreimaster residuals



run 1020, chip 146, turn 8°

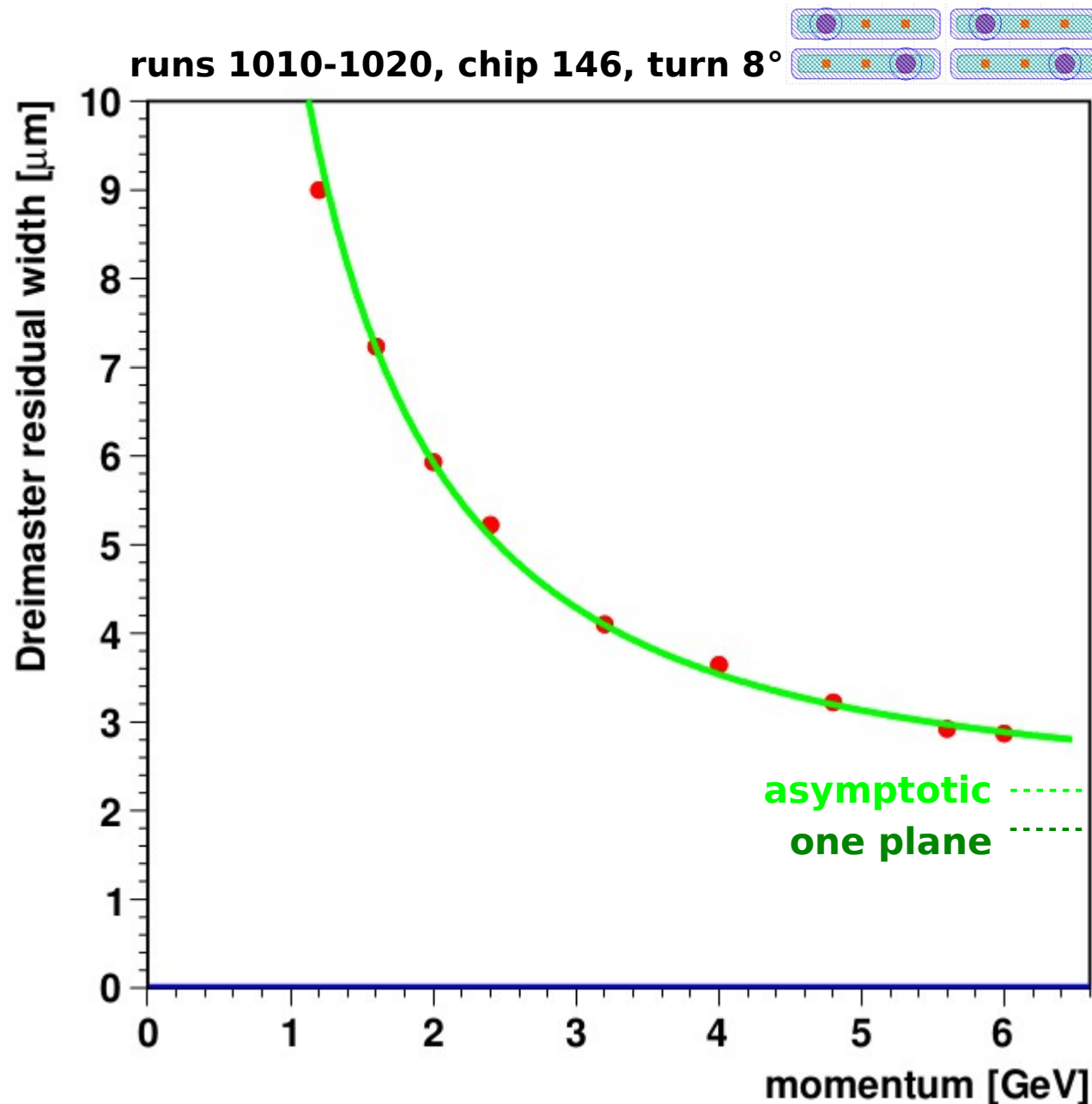
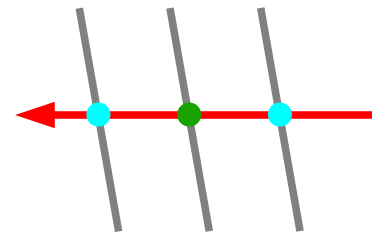


track



- pixel pitch 25 μm
- turn 8° (150 μm thick)
- Landau peak clusters
- 6 GeV
- Triplet residuals:
 - $\Delta x = x_B - \frac{x_A + x_C}{2}$
 - **fit: 2.74 μm**
 - **unfolding tracking and scattering: 1.8 μm hit resolution**

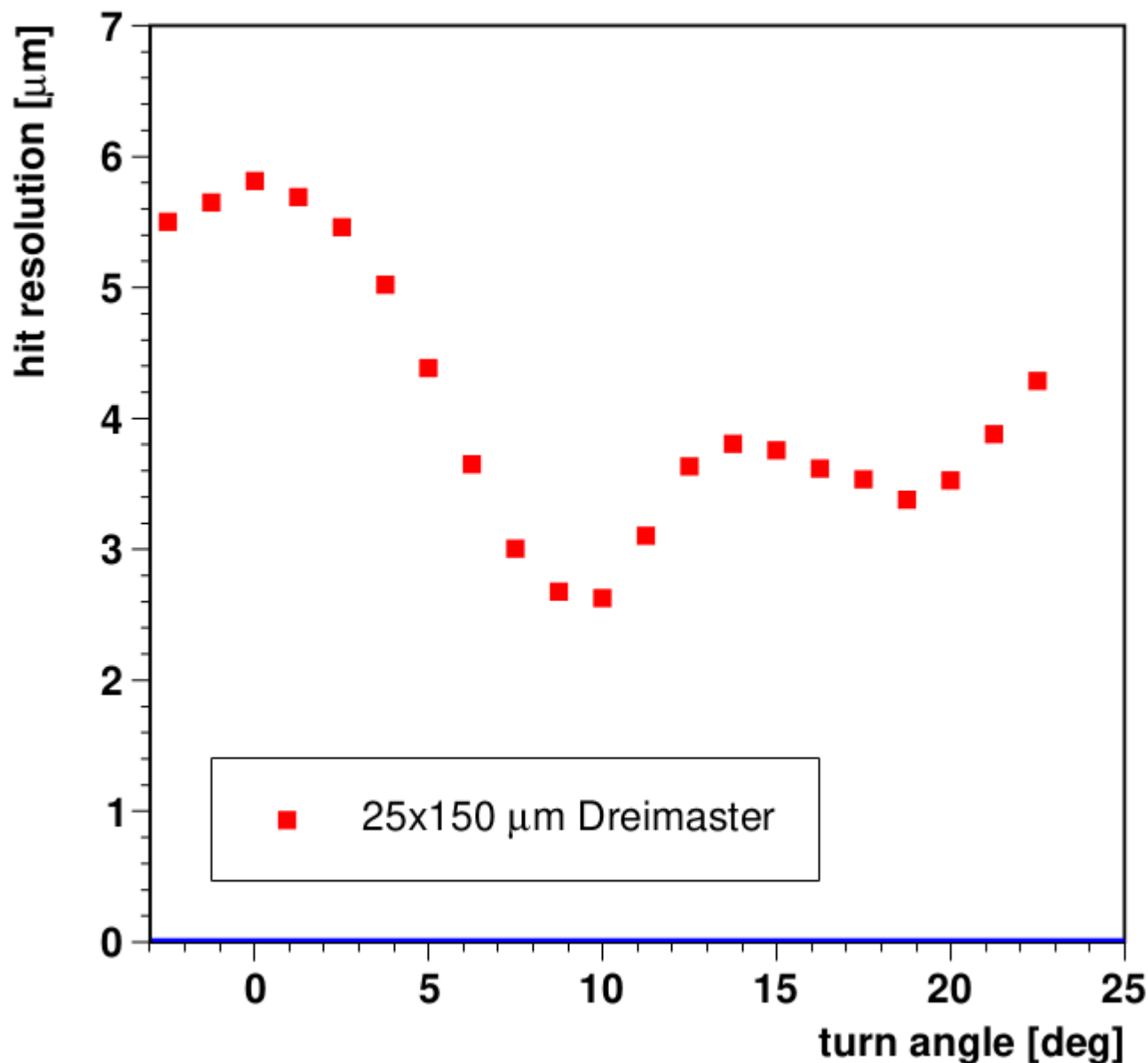
momentum scan



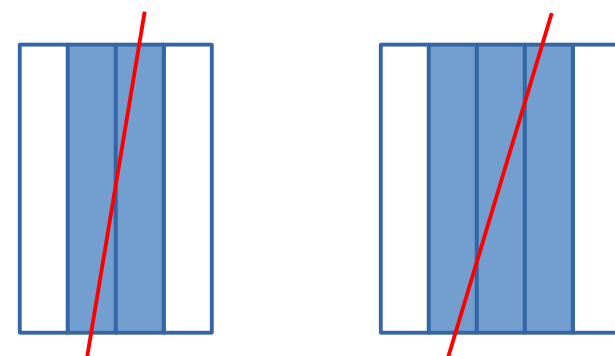
- unfold resolution and multiple scattering:
 - momentum scan
- **fit:**
 - **residual² = (scattering / p)² + resolution²**
 - **triplet resolution: 2.2 μm**
 - **single plane resolution: 1.8 μm**

Dreimaster: turn scan

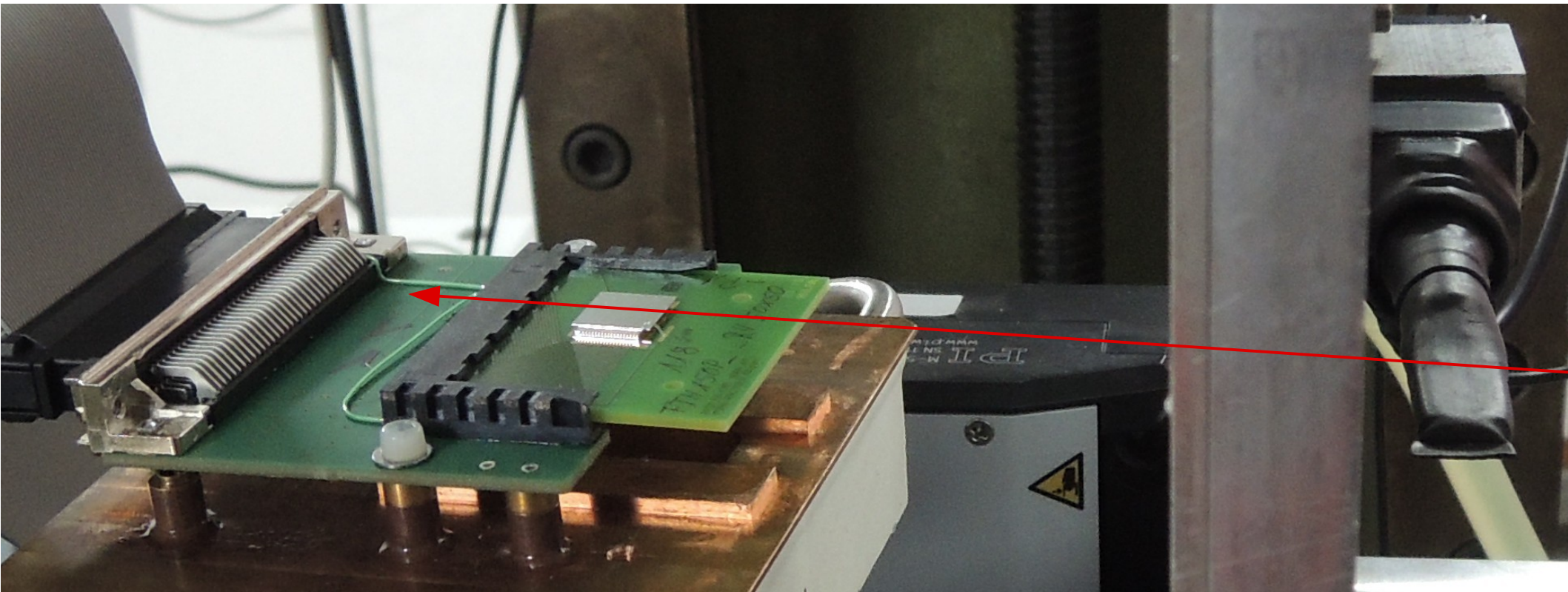
Dreimaster, 25x150 μm , 5.6 GeV, runs 1757-77



- **25×150 μm sensors:**
 - Dreimaster triplet
- fresh
- optimal resolution at:
 - $\text{atan}(25/150) = 9.5^\circ$
- 2nd minimum:
 - $\text{atan}(50/150) = 18.4^\circ$



rotated edge-on tracking

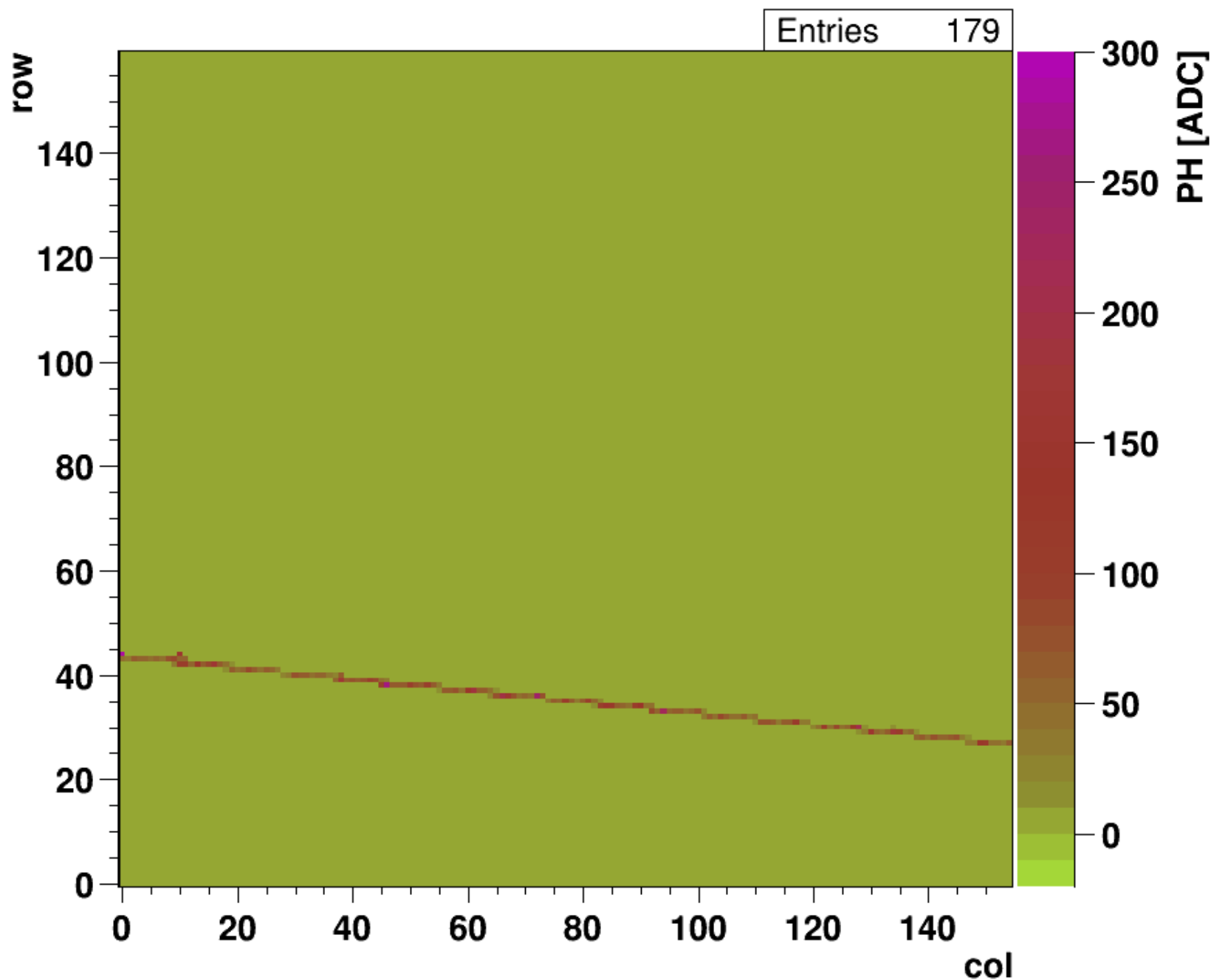


Planar pixel sensor with ROC4Sens readout
mounted on a rotation stage

beam: edge-on

edge-on track

**50×50 μm
pixels**

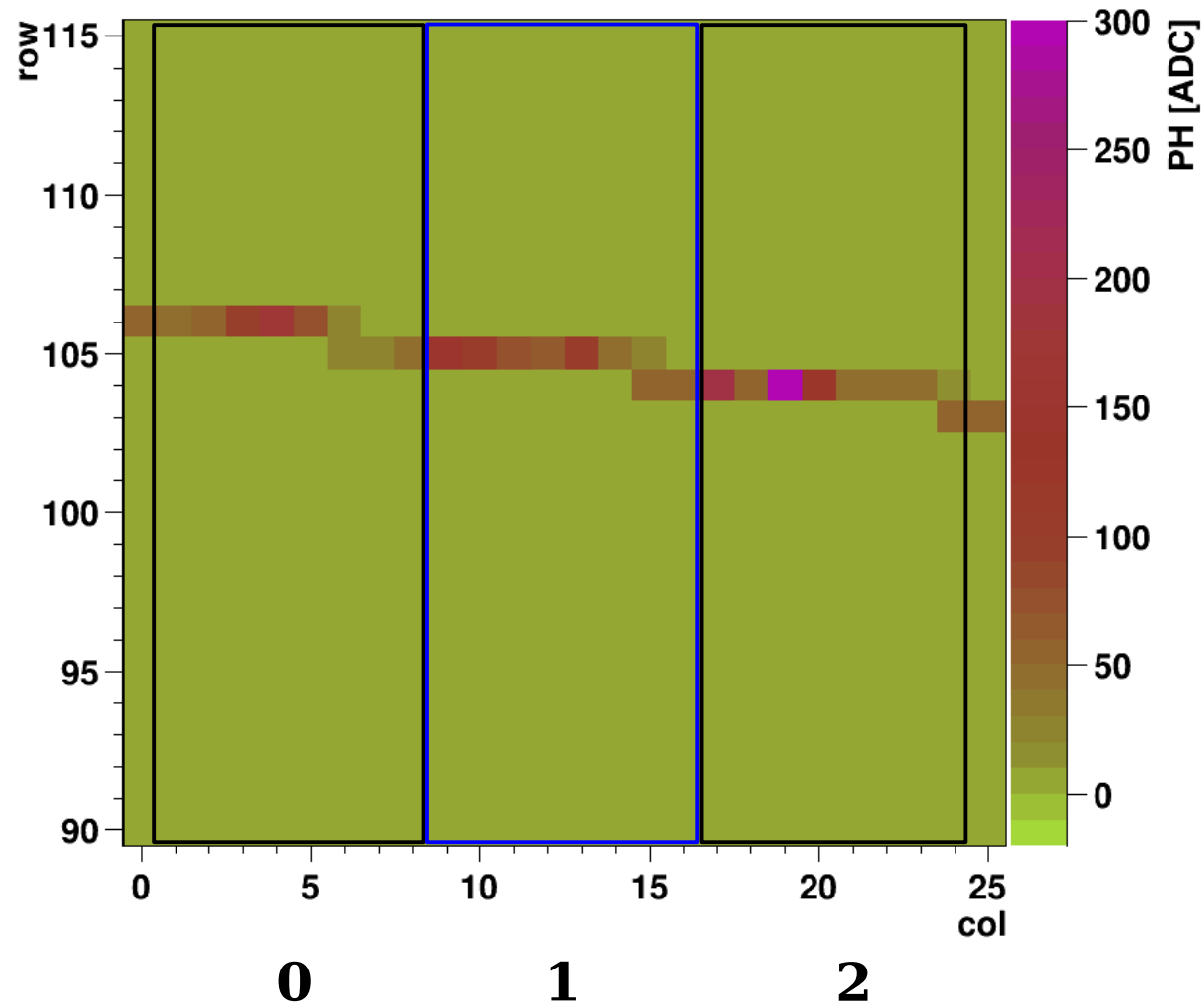


rotated edge-on combined tracking

- small turn angle
- combine neighbouring columns into one measurement:
 - effective thicker sensor
- triplet tracking:

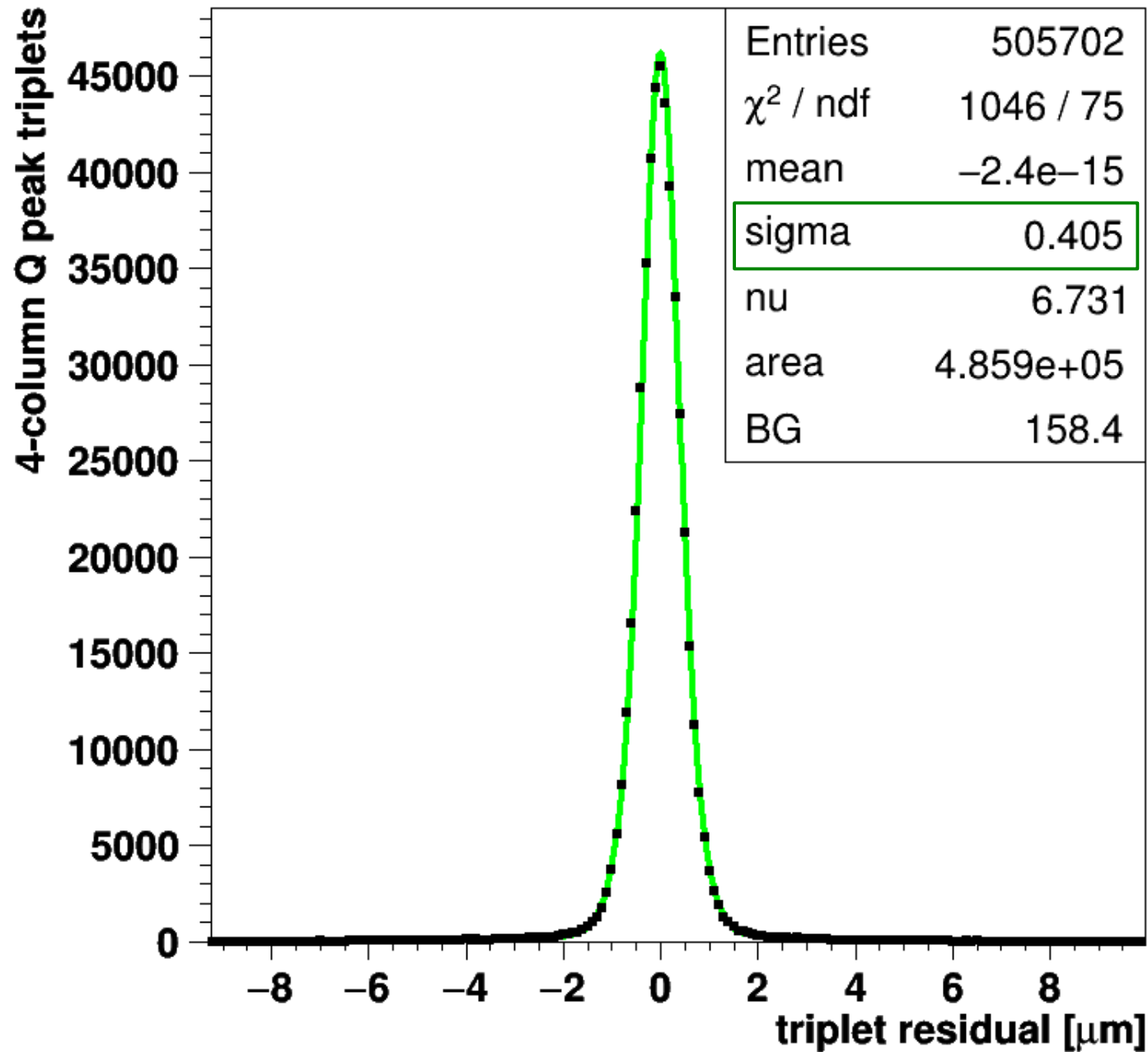
$$\Delta y = y_1 - \frac{y_0 + y_2}{2}$$

$$\sigma(\Delta y) = \sigma(y) \cdot \sqrt{3/2}$$



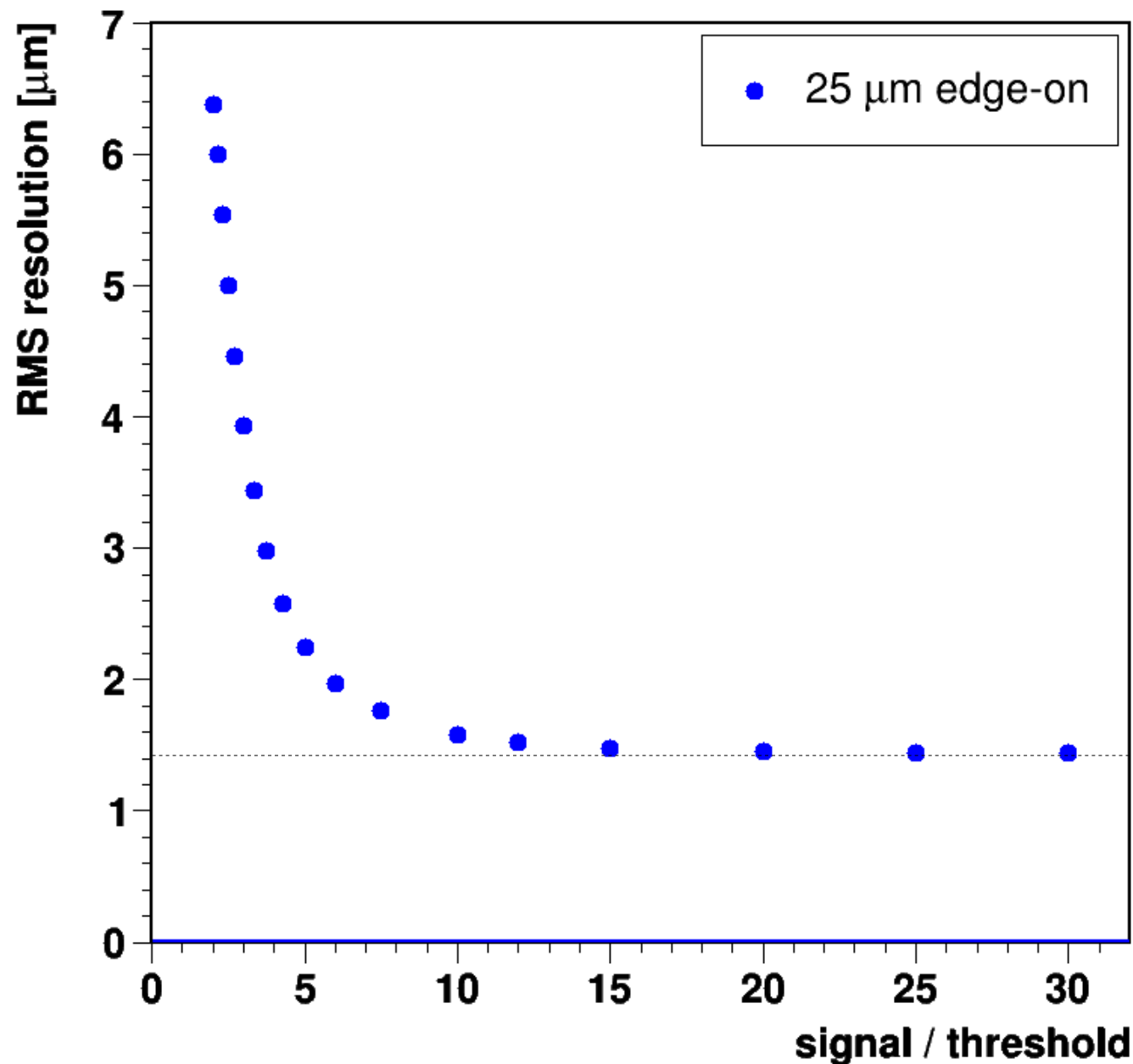
edge-on residuals

run 4693, PSI 25-06, edge-on, turn 1.6



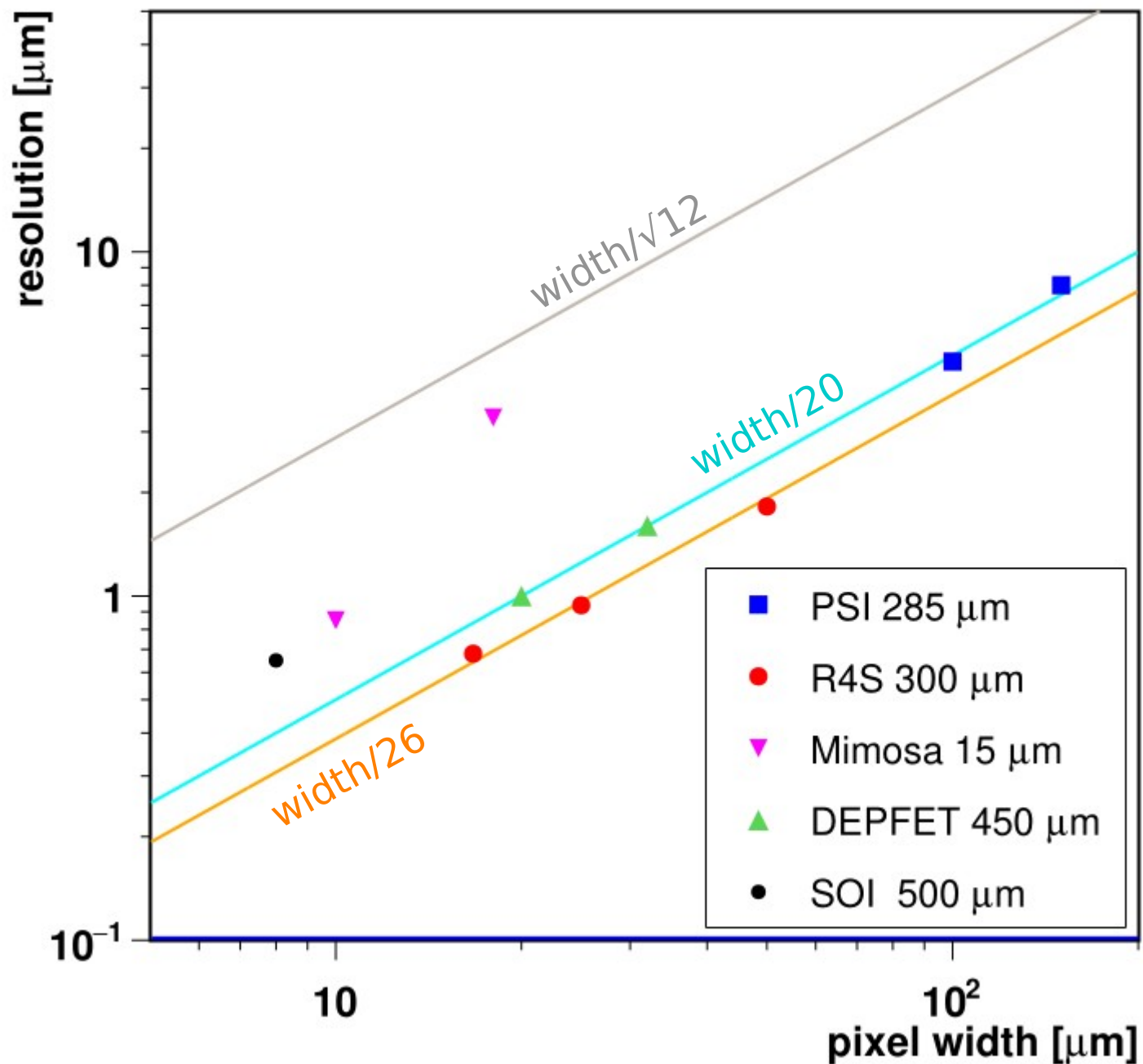
- **$150 \times 17 \mu\text{m}$ pixels**
 - edge-on with 1.6° turn angle
 - combine 4 columns
 - Landau peak
- triplet residual:
 - **width $0.4 \mu\text{m}$**
- $\Rightarrow$ single hit:
 - **$0.33 \mu\text{m}$**
 - **the best ever?**

resolution vs threshold



- **25 μm pixels**
 - edge-on
 - optimal turn angle
- threshold applied offline
- need:
 - threshold < 0.1 signal
 - for best resolution

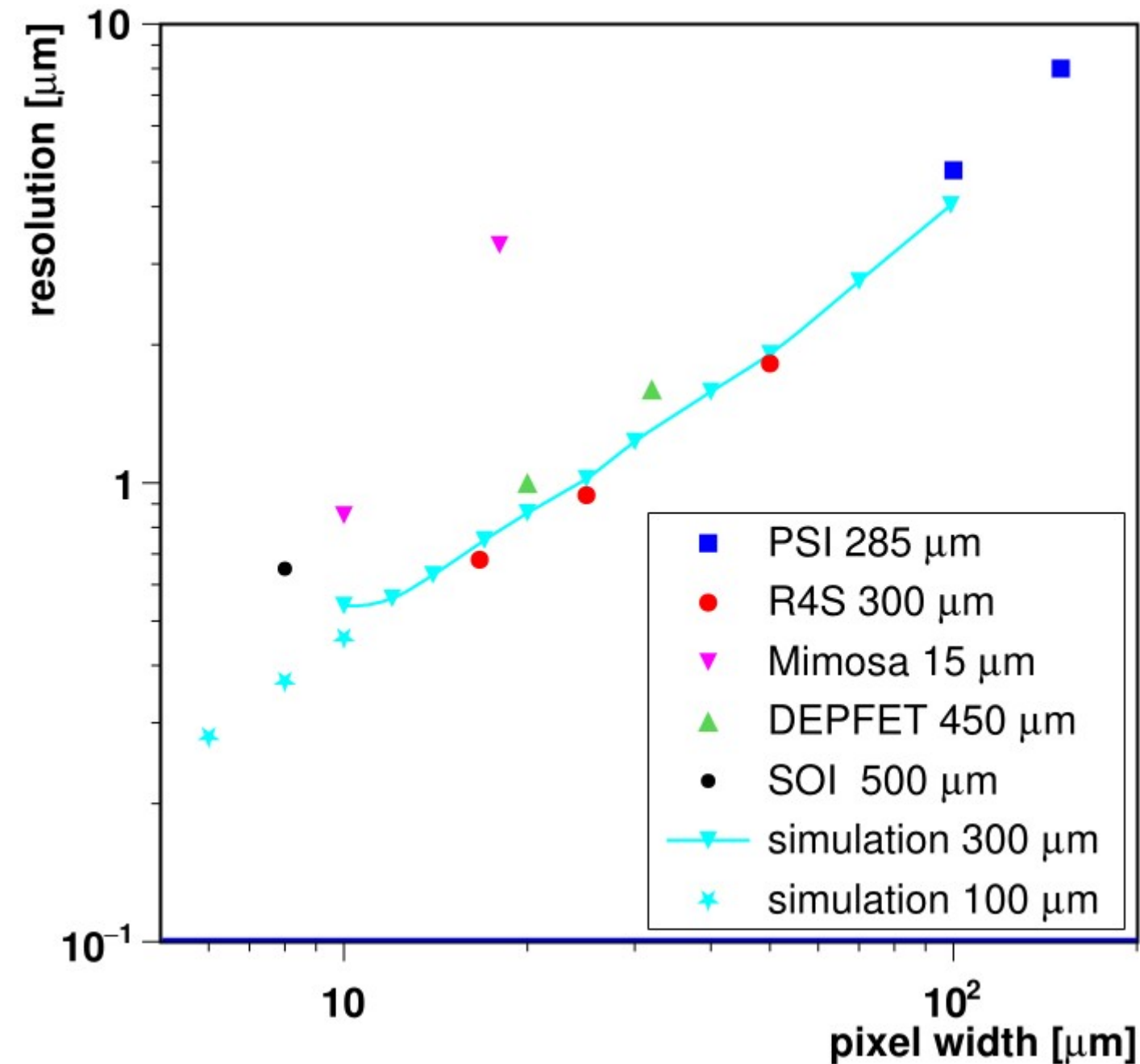
resolution vs pixel geometry



- a composition of measurements
 - with lines to guide the eye
- most at optimal incidence angle

thickness

data vs simulation

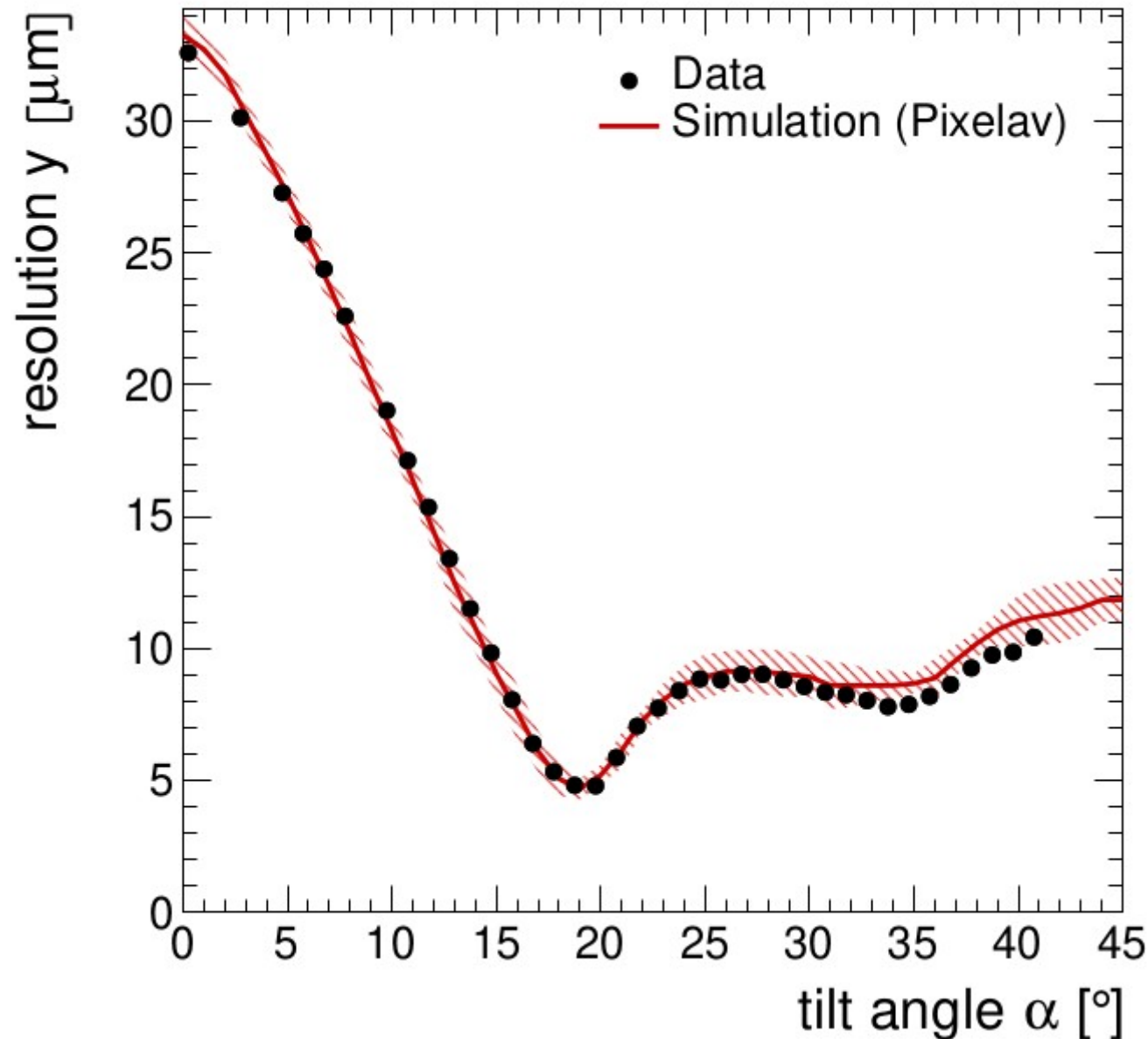


- Bichsel simulation:
 - incident angle
 - ionization fluctuations
 - diffusion
- **need thinner sensors to avoid diffusion limit**
- **edge-on data:**
 - **better than simulation?**

- position resolution scales with pixel size:
 - from 150 to 17 μm
- with signal / threshold ≈ 10 :
 - resolution $\approx \text{pitch} / 20$ (at optimal incidence angle)
- edge-on telescope-on-a-chip:
 - resolution 0.4 μm for 17 μm pixels at 600 μm thickness
 - (better than simulation? correlation?)
- to do:
 - Dreimaster with 17 μm pixels
- another talk:
 - sensor simulation details

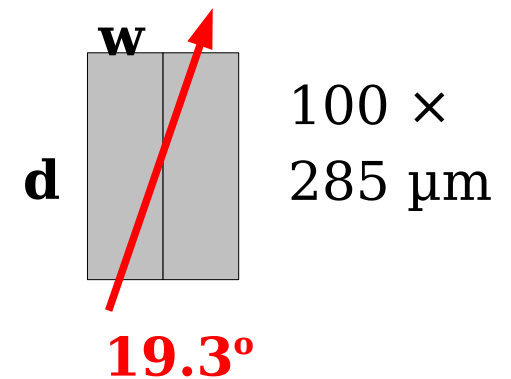
resolution vs tilt angle

3.0×10^6 tracks (5.6 GeV)



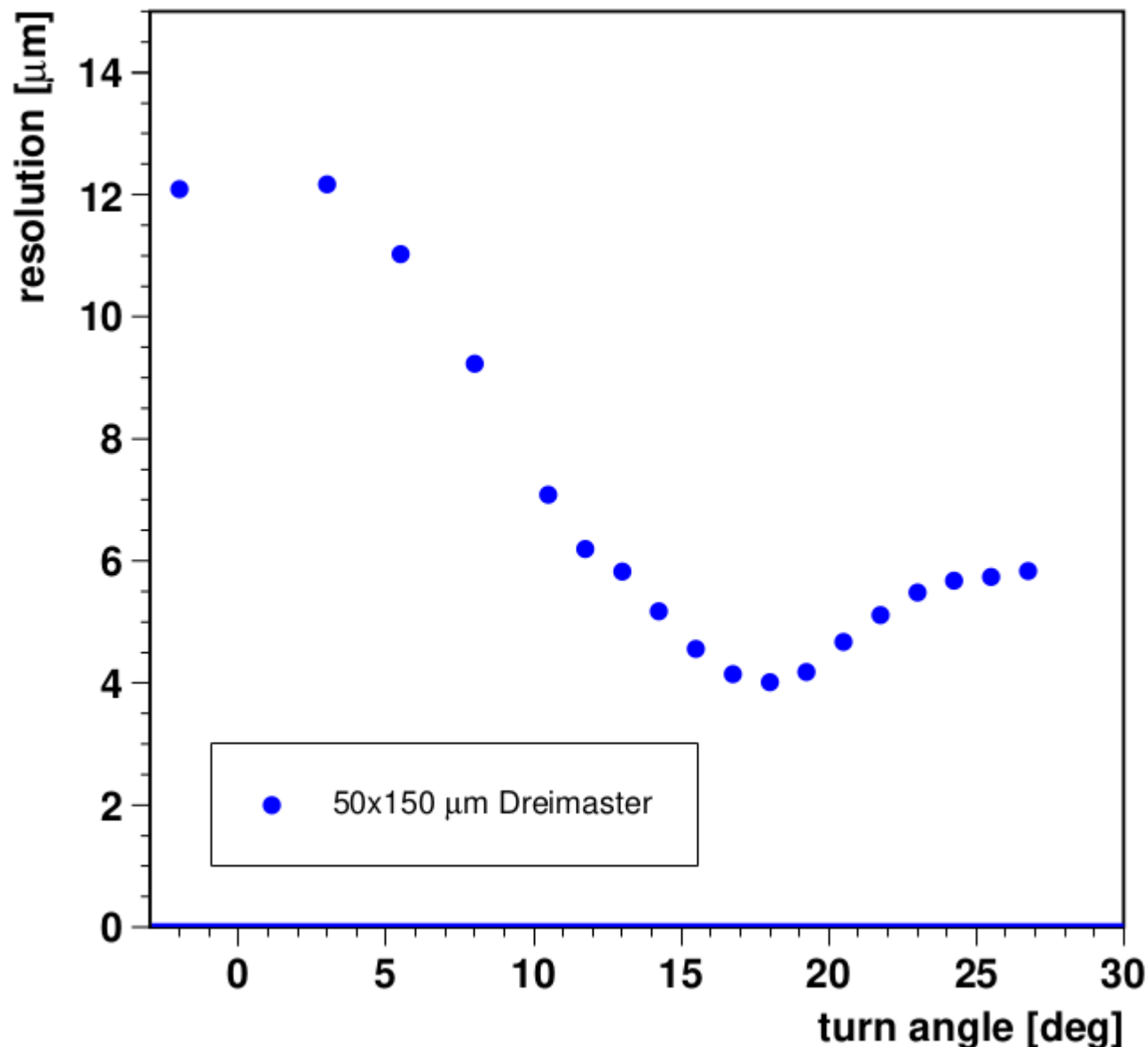
- **100 μm pixels**
 - thickness 285 μm
 - threshold 1.5 ke
- minimum:
 - **4.8 μm at 19.5°**
 - (at the Landau peak)

best tilt = $\text{atan}(w/d)$

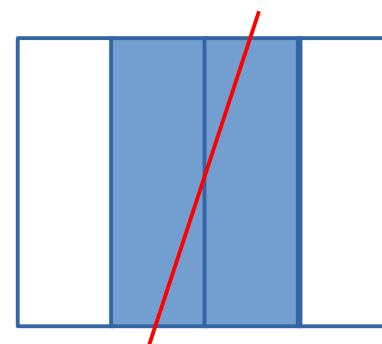


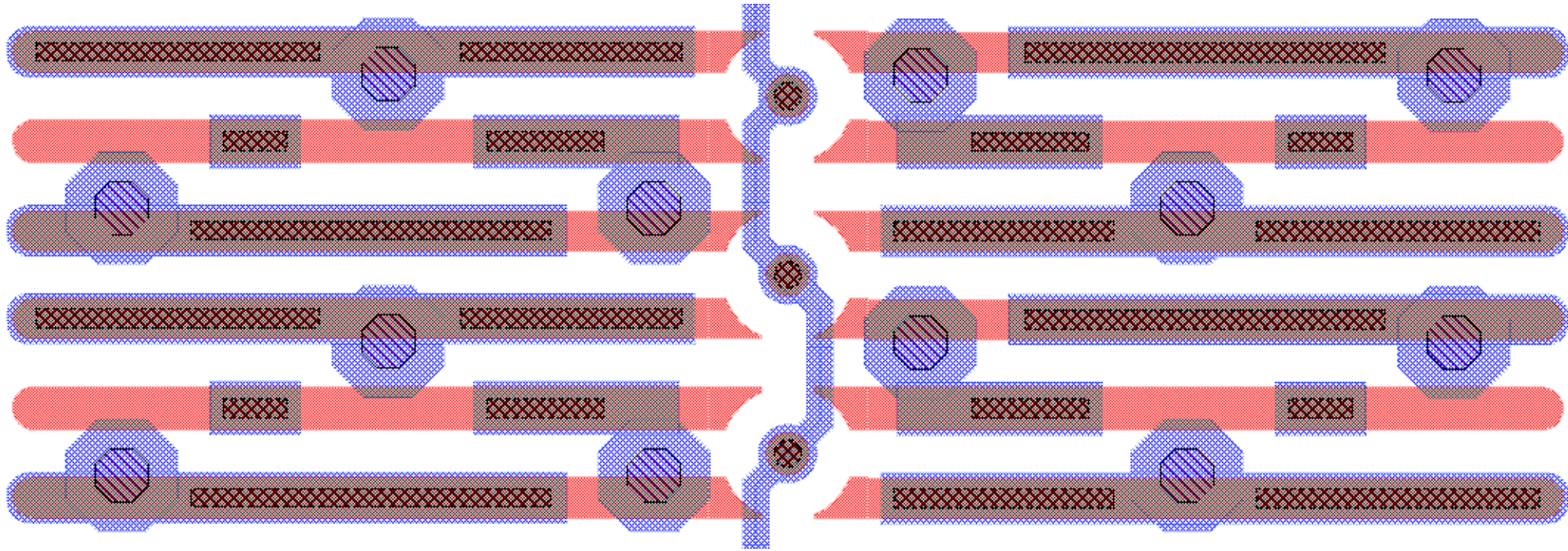
Dreimaster: turn scan

Dreimaster, 50x150 μm , 5.6 GeV, runs 1873-93



- **50×150 μm pixel sensors:**
 - Dreimaster triplet residuals
- fresh
- optimal resolution at:
 - $\text{atan}(50/150) = 18.4^\circ$





- $150 \times 16.7 \mu\text{m}$ pixels
 - design by T. Rohe, PSI
 - with bias dots
 - mapped to 50×50 ROC4Sens
 - bump bond pad overlap induces cross talk

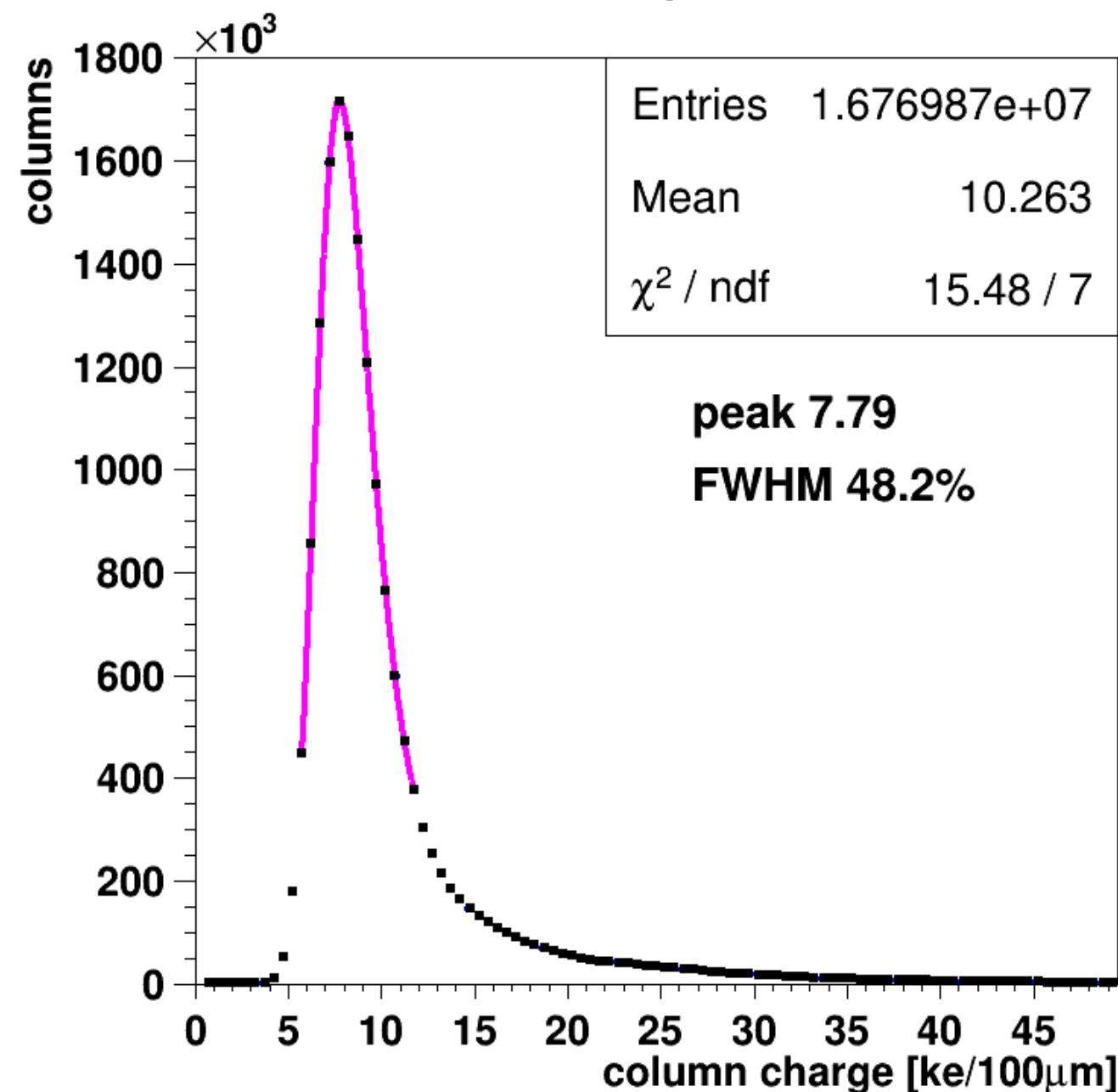
edge-on setup



parasitic downstream setup in TB22, without telescope

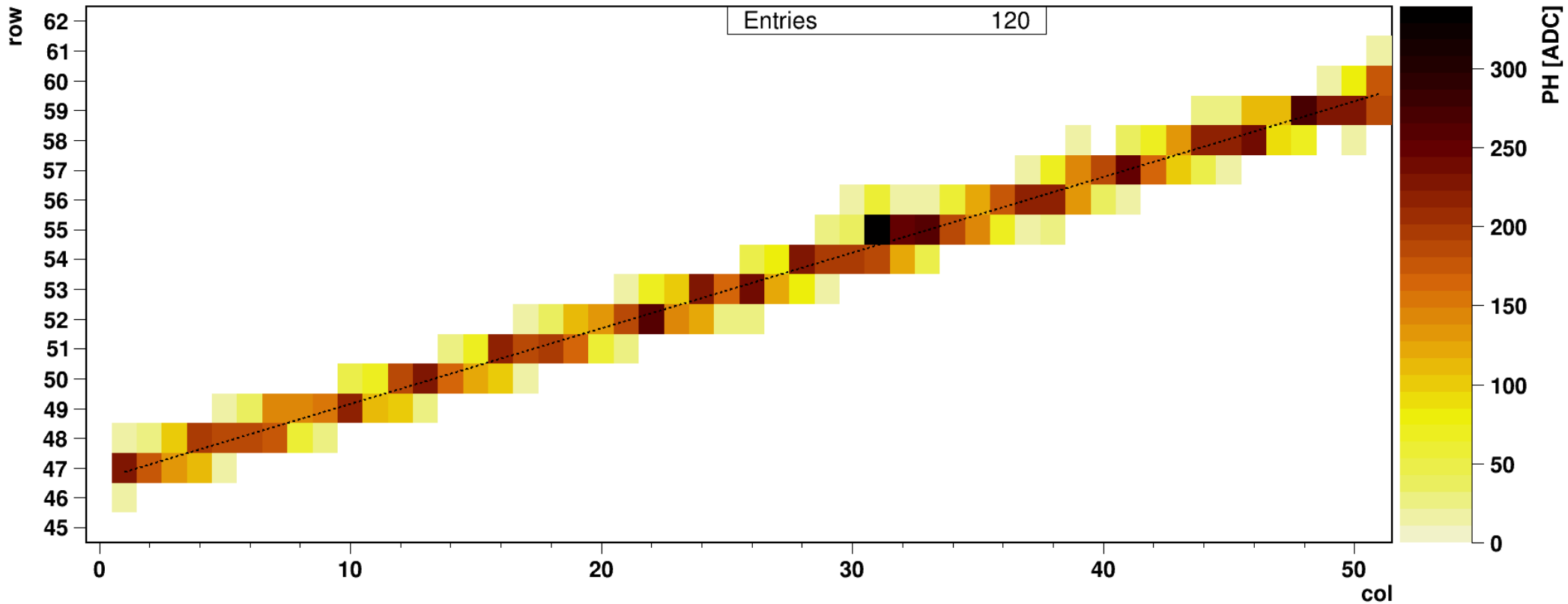
edge-on charge distribution

run 4693, PSI 25-06, edge-on, turn 1.6



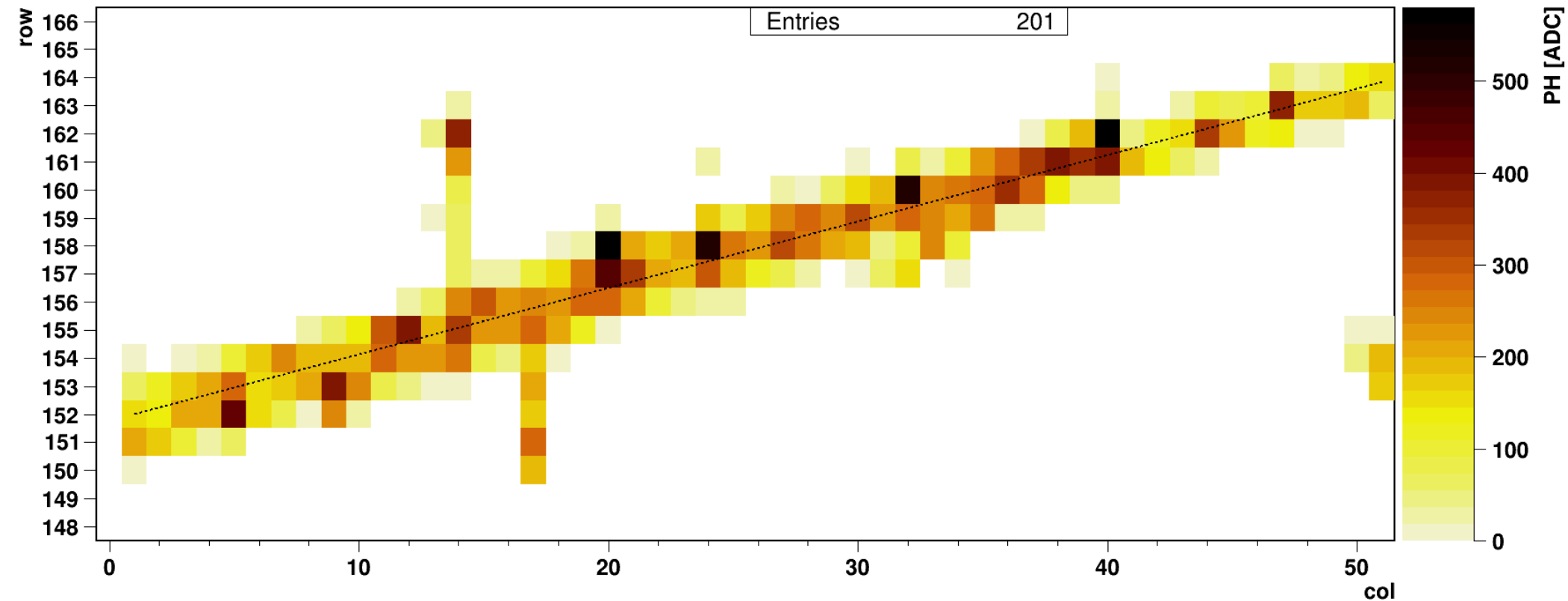
- **charge distribution**
 - **normalized to 100 μm**
- **tail = delta rays**

edge-on track



- $150 \times 17 \mu\text{m}$ pixels
- turn angle 1.6°
 - track changes row every 4th pixel
 - 'telescope-on-a-chip'

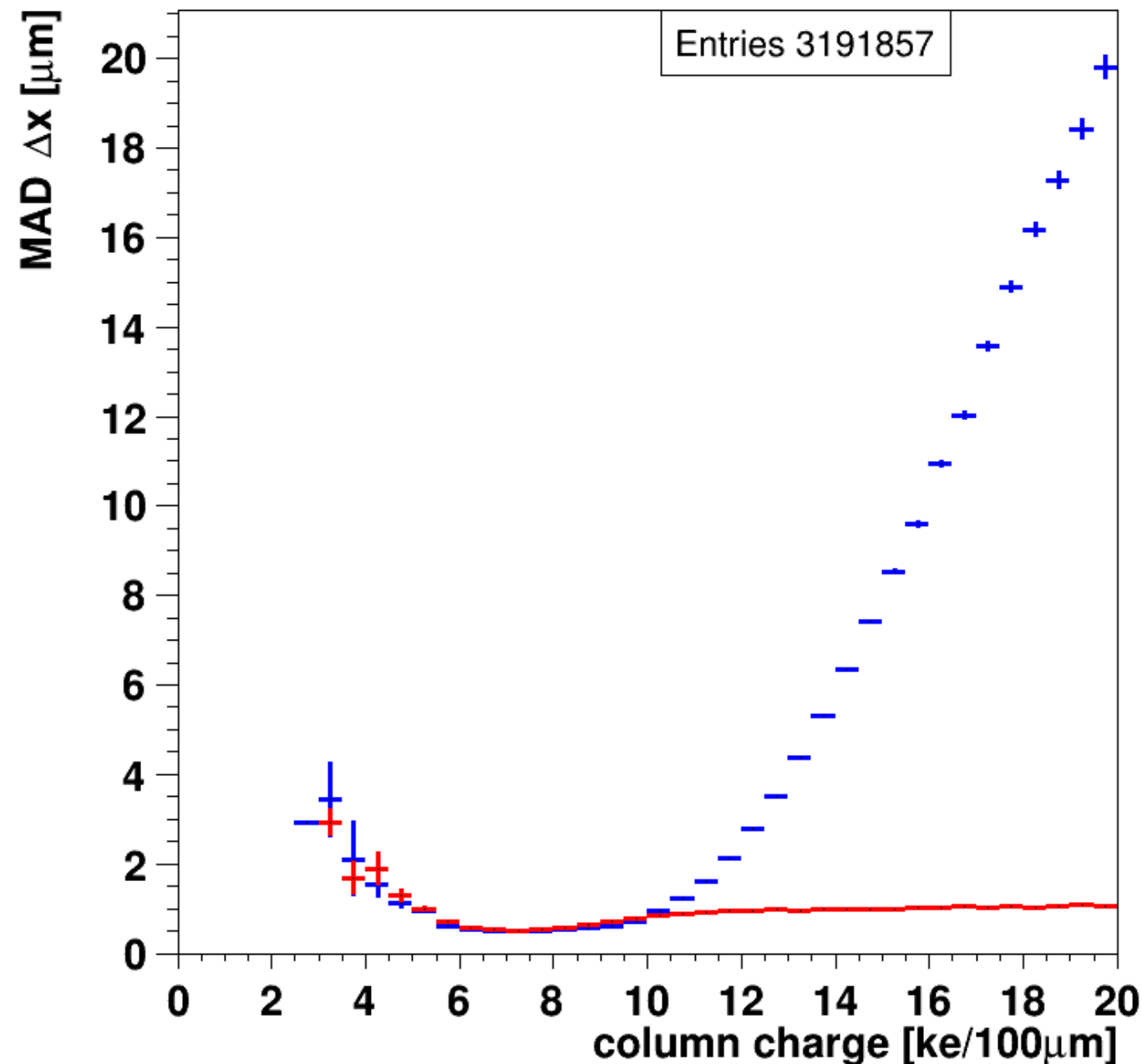
edge-on track



- most delta rays are emitted near 90°
 - omit columns with large charge
 - remaining pixel group has good resolution

position resolution

run 4693, PSI 25-06, edge-on, turn 1.6



- **MAD = mean absolute deviation**
 - measures width of a distribution
- suppression of delta rays stabilizes resolution

ROC4sens

0.25 μm
IBM
CMOS

